



# LPC11Cx2/Cx4

32-bit ARM Cortex-M0 microcontroller; 16/32 kB flash, 8 kB SRAM; C\_CAN

Rev. 3.2 — 4 January 2016

Product data sheet

## 1. General description

The LPC11Cx2/Cx4 are an ARM Cortex-M0 based, low-cost 32-bit MCU family, designed for 8/16-bit microcontroller applications, offering performance, low power, simple instruction set and memory addressing together with reduced code size compared to existing 8/16-bit architectures.

The LPC11Cx2/Cx4 operate at CPU frequencies of up to 50 MHz.

The peripheral complement of the LPC11Cx2/Cx4 includes 16/32 kB of flash memory, 8 kB of data memory, one C\_CAN controller, one Fast-mode Plus I<sup>2</sup>C-bus interface, one RS-485/EIA-485 UART, two SPI interfaces with SSP features, four general purpose counter/timers, a 10-bit ADC, and up to 40 general purpose I/O pins.

On-chip C\_CAN drivers and flash In-System Programming tools via C\_CAN are included. In addition, the LPC11C22 and LPC11C24 parts include an on-chip, high-speed CAN transceiver.

## 2. Features and benefits

- System:
  - ◆ ARM Cortex-M0 processor, running at frequencies of up to 50 MHz.
  - ◆ ARM Cortex-M0 built-in Nested Vectored Interrupt Controller (NVIC).
  - ◆ Serial Wire Debug.
  - ◆ System tick timer.
- Memory:
  - ◆ 32 kB (LPC11Cx4) or 16 kB (LPC11Cx2) on-chip flash program memory.
  - ◆ 8 kB SRAM data memory.
  - ◆ In-System Programming (ISP) and In-Application Programming (IAP) via on-chip bootloader software.
  - ◆ Flash ISP commands can be issued via UART or C\_CAN.
- Digital peripherals:
  - ◆ General Purpose I/O (GPIO) pins with configurable pull-up/pull-down resistors.
  - ◆ 40 GPIO pins on the LPC11C12/C14 parts; 36 GPIO pins on the LPC11C22/C24 parts.
  - ◆ GPIO pins can be used as edge and level sensitive interrupt sources.
  - ◆ High-current output driver (20 mA) on one pin.
  - ◆ High-current sink drivers (20 mA) on two I<sup>2</sup>C-bus pins in Fast-mode Plus.
  - ◆ Four general purpose counter/timers with a total of four capture inputs and 13 (LPC11C12/C14) or 12 (LPC11C22/C24) match outputs.



- ◆ Programmable WatchDog Timer (WDT).
- Analog peripherals:
  - ◆ 10-bit ADC with input multiplexing among 8 pins.
- Serial interfaces:
  - ◆ UART with fractional baud rate generation, internal FIFO, and RS-485 support.
  - ◆ Two SPI controllers with SSP features and with FIFO and multi-protocol capabilities.
  - ◆ I<sup>2</sup>C-bus interface supporting full I<sup>2</sup>C-bus specification and Fast-mode Plus with a data rate of 1 Mbit/s with multiple address recognition and monitor mode.
  - ◆ C\_CAN controller. On-chip C\_CAN and CANopen drivers included.
  - ◆ On-chip, high-speed CAN transceiver (parts LPC11C22/C24 only).
- Clock generation:
  - ◆ 12 MHz internal RC oscillator trimmed to 1 % accuracy that can optionally be used as a system clock.
  - ◆ Crystal oscillator with an operating range of 1 MHz to 25 MHz.
  - ◆ Programmable watchdog oscillator with a frequency range of 7.8 kHz to 1.8 MHz.
  - ◆ PLL allows CPU operation up to the maximum CPU rate without the need for a high-frequency crystal. May be run from the system oscillator or the internal RC oscillator.
  - ◆ Clock output function with divider that can reflect the system oscillator, IRC, CPU clock, or the Watchdog clock.
- Power control:
  - ◆ Integrated PMU (Power Management Unit) to minimize power consumption during Sleep, Deep-sleep, and Deep power-down modes.
  - ◆ Three reduced power modes: Sleep, Deep-sleep, and Deep power-down.
  - ◆ Processor wake-up from Deep-sleep mode via a dedicated start logic using 13 of the GPIO pins.
  - ◆ Power-On Reset (POR).
  - ◆ Brownout detect with four separate thresholds for interrupt and forced reset.
- Unique device serial number for identification.
- Single 3.3 V power supply (1.8 V to 3.6 V).
- Available as 48-pin LQFP package.

### 3. Applications

- |                    |  |
|--------------------|--|
| ■ eMetering        | ■ Industrial and sensor based networks |
| ■ Elevator systems | ■ White goods                          |

## 4. Ordering information

**Table 1. Ordering information**

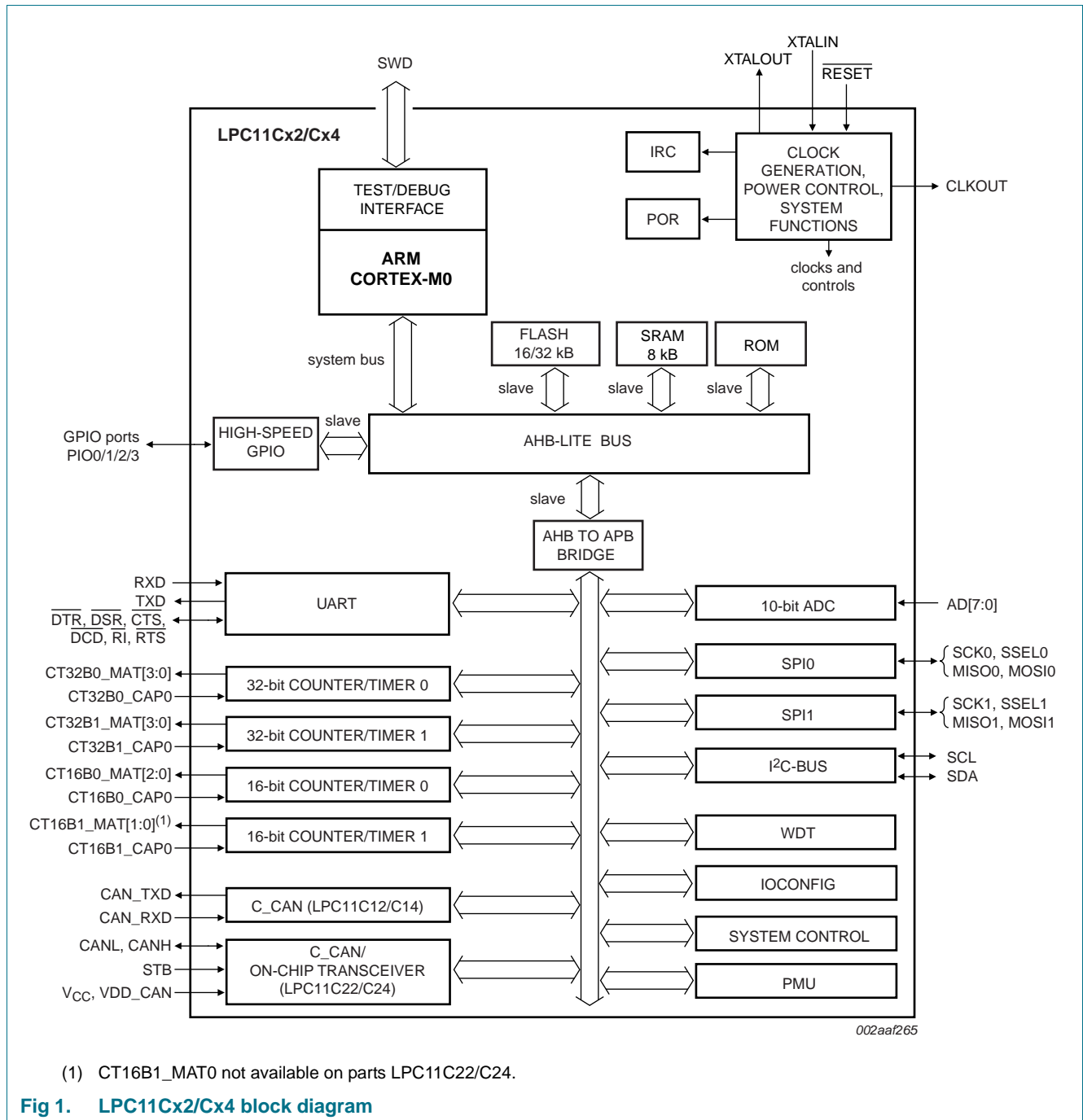
Type number	Package		
	Name	Description	Version
LPC11C12FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC11C14FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC11C22FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC11C24FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

### 4.1 Ordering options

**Table 2. Ordering options**

Type number	Flash	Total SRAM	UART RS-485	I <sup>2</sup> C/ Fast+	SPI	C_CAN	C_CAN with on-chip CAN transceiver	GPIO pins	ADC channels	Package
LPC11C12FBD48/301	16 kB	8 kB	1	1	2	1	no	40	8	LQFP48
LPC11C14FBD48/301	32 kB	8 kB	1	1	2	1	no	40	8	LQFP48
LPC11C22FBD48/301	16 kB	8 kB	1	1	2	1	yes	36	8	LQFP48
LPC11C24FBD48/301	32 kB	8 kB	1	1	2	1	yes	36	8	LQFP48

## 5. Block diagram



6. Pinning information

6.1 Pinning

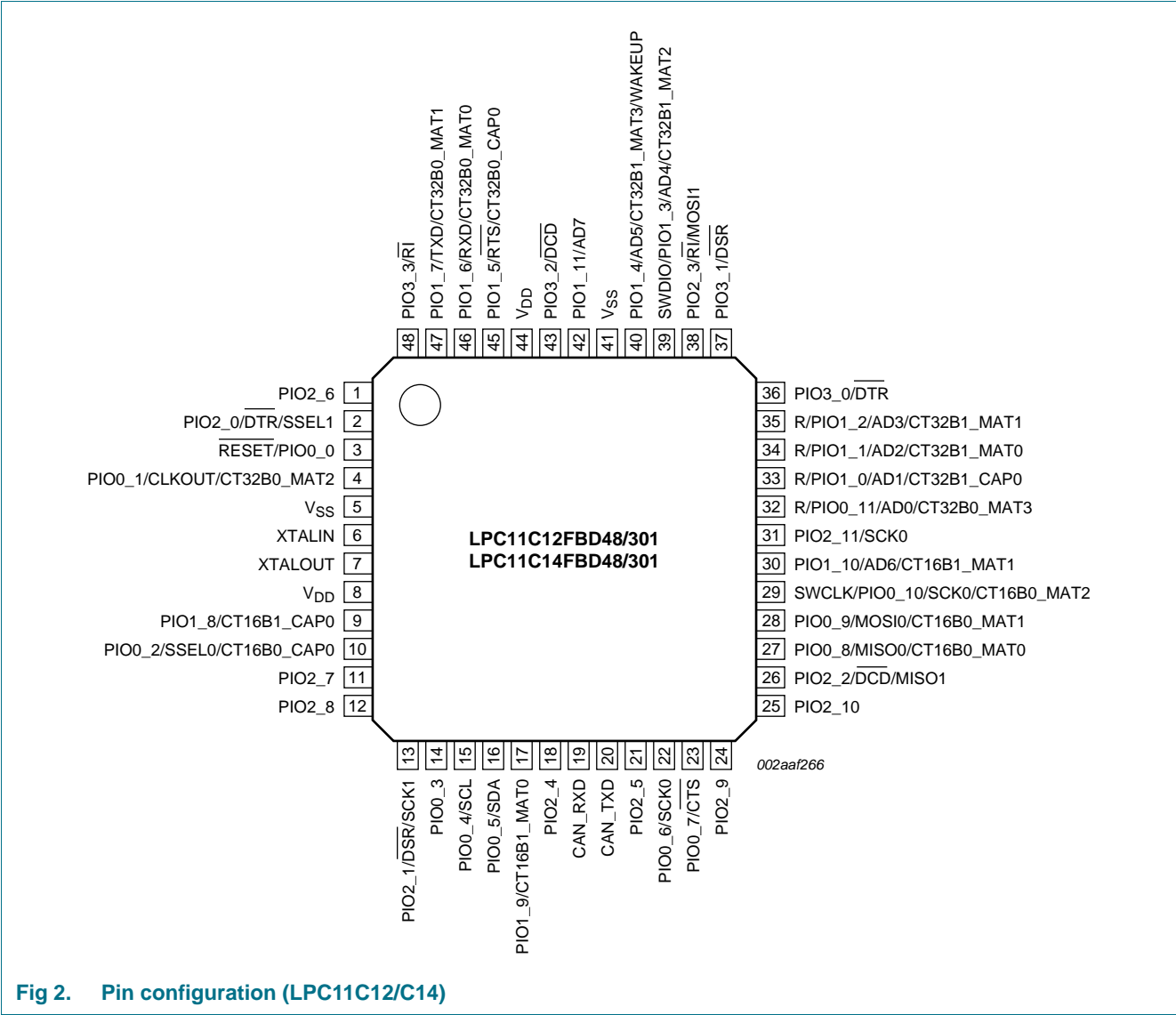


Fig 2. Pin configuration (LPC11C12/C14)

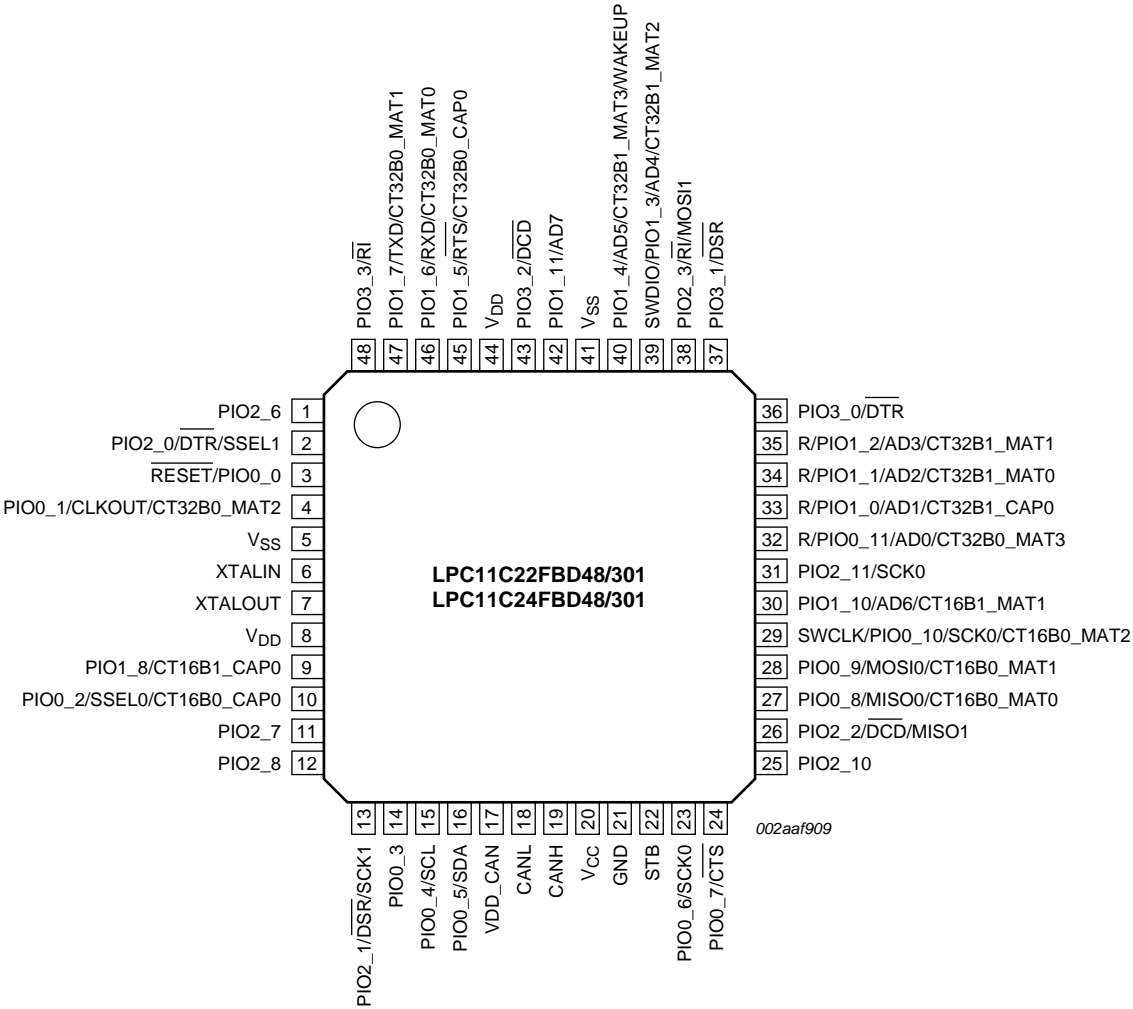


Fig 3. Pin configuration (LPC11C22/C24)

## 6.2 Pin description

**Table 3.** LPC11C12/C14 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO0_0 to PIO0_11					<b>Port 0</b> — Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.
RESET/PIO0_0	3[2]	yes	I	I; PU	<b>RESET</b> — External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
			I/O	-	<b>PIO0_0</b> — General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/CT32B0_MAT2	4[3]	yes	I/O	I; PU	<b>PIO0_1</b> — General purpose digital input/output pin. A LOW level on this pin during reset starts the flash ISP command handler via UART (if PIO0_3 is HIGH) or via C_CAN (if PIO0_3 is LOW).
			O	-	<b>CLKOUT</b> — Clockout pin.
			O	-	<b>CT32B0_MAT2</b> — Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/CT16B0_CAP0	10[3]	yes	I/O	I; PU	<b>PIO0_2</b> — General purpose digital input/output pin.
			I/O	-	<b>SSEL0</b> — Slave Select for SPI0.
			I	-	<b>CT16B0_CAP0</b> — Capture input 0 for 16-bit timer 0.
PIO0_3	14[3]	yes	I/O	I; PU	<b>PIO0_3</b> — General purpose digital input/output pin. This pin is monitored during reset: Together with a LOW level on pin PIO0_1, a LOW level starts the flash ISP command handler via C_CAN and a HIGH level starts the flash ISP command handler via UART.
PIO0_4/SCL	15[4]	yes	I/O	I; IA	<b>PIO0_4</b> — General purpose digital input/output pin (open-drain).
			I/O	-	<b>SCL</b> — I <sup>2</sup> C-bus, open-drain clock input/output. High-current sink only if I <sup>2</sup> C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	16[4]	yes	I/O	I; IA	<b>PIO0_5</b> — General purpose digital input/output pin (open-drain).
			I/O	-	<b>SDA</b> — I <sup>2</sup> C-bus, open-drain data input/output. High-current sink only if I <sup>2</sup> C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/SCK0	22[3]	yes	I/O	I; PU	<b>PIO0_6</b> — General purpose digital input/output pin.
			I/O	-	<b>SCK0</b> — Serial clock for SPI0.
PIO0_7/CTS	23[3]	yes	I/O	I; PU	<b>PIO0_7</b> — General purpose digital input/output pin (high-current output driver).
			I	-	<b>CTS</b> — Clear To Send input for UART.
PIO0_8/MISO0/CT16B0_MAT0	27[3]	yes	I/O	I; PU	<b>PIO0_8</b> — General purpose digital input/output pin.
			I/O	-	<b>MISO0</b> — Master In Slave Out for SPI0.
			O	-	<b>CT16B0_MAT0</b> — Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/CT16B0_MAT1	28[3]	yes	I/O	I; PU	<b>PIO0_9</b> — General purpose digital input/output pin.
			I/O	-	<b>MOSI0</b> — Master Out Slave In for SPI0.
			O	-	<b>CT16B0_MAT1</b> — Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/SCK0/CT16B0_MAT2	29[3]	yes	I	I; PU	<b>SWCLK</b> — Serial wire clock.
			I/O	-	<b>PIO0_10</b> — General purpose digital input/output pin.
			I/O	-	<b>SCK0</b> — Serial clock for SPI0.
			O	-	<b>CT16B0_MAT2</b> — Match output 2 for 16-bit timer 0.

Table 3. LPC11C12/C14 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
R/PIO0_11/ AD0/ CT32B0_MAT3	32[5]	yes	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO0_11</b> — General purpose digital input/output pin.
			I	-	<b>AD0</b> — A/D converter, input 0.
			O	-	<b>CT32B0_MAT3</b> — Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_11					<b>Port 1</b> — Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/AD1/ CT32B1_CAP0	33[5]	yes	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_0</b> — General purpose digital input/output pin.
			I	-	<b>AD1</b> — A/D converter, input 1.
			I	-	<b>CT32B1_CAP0</b> — Capture input 0 for 32-bit timer 1.
R/PIO1_1/AD2/ CT32B1_MAT0	34[5]	no	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_1</b> — General purpose digital input/output pin.
			I	-	<b>AD2</b> — A/D converter, input 2.
			O	-	<b>CT32B1_MAT0</b> — Match output 0 for 32-bit timer 1.
R/PIO1_2/AD3/ CT32B1_MAT1	35[5]	no	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_2</b> — General purpose digital input/output pin.
			I	-	<b>AD3</b> — A/D converter, input 3.
			O	-	<b>CT32B1_MAT1</b> — Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/ CT32B1_MAT2	39[5]	no	I/O	I; PU	<b>SWDIO</b> — Serial wire debug input/output.
			I/O	-	<b>PIO1_3</b> — General purpose digital input/output pin.
			I	-	<b>AD4</b> — A/D converter, input 4.
			O	-	<b>CT32B1_MAT2</b> — Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	no	I/O	I; PU	<b>PIO1_4</b> — General purpose digital input/output pin with 10 ns glitch filter.
			I	-	<b>AD5</b> — A/D converter, input 5.
			O	-	<b>CT32B1_MAT3</b> — Match output 3 for 32-bit timer 1.
			I	-	<b>WAKEUP</b> — Deep power-down mode wake-up pin with 20 ns glitch filter. This pin must be pulled HIGH externally to enter Deep power-down mode and pulled LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
PIO1_5/RTS/ CT32B0_CAP0	45[3]	no	I/O	I; PU	<b>PIO1_5</b> — General purpose digital input/output pin.
			O	-	<b>RTS</b> — Request To Send output for UART.
			I	-	<b>CT32B0_CAP0</b> — Capture input 0 for 32-bit timer 0.
PIO1_6/RXD/ CT32B0_MAT0	46[3]	no	I/O	I; PU	<b>PIO1_6</b> — General purpose digital input/output pin.
			I	-	<b>RXD</b> — Receiver input for UART.
			O	-	<b>CT32B0_MAT0</b> — Match output 0 for 32-bit timer 0.



Table 3. LPC11C12/C14 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO1_7/TXD/CT32B0_MAT1	47[3]	no	I/O	I; PU	<b>PIO1_7</b> — General purpose digital input/output pin.
			O	-	<b>TXD</b> — Transmitter output for UART.
			O	-	<b>CT32B0_MAT1</b> — Match output 1 for 32-bit timer 0.
PIO1_8/CT16B1_CAP0	9[3]	no	I/O	I; PU	<b>PIO1_8</b> — General purpose digital input/output pin.
			I	-	<b>CT16B1_CAP0</b> — Capture input 0 for 16-bit timer 1.
PIO1_9/CT16B1_MAT0	17[3]	no	I/O	I; PU	<b>PIO1_9</b> — General purpose digital input/output pin.
			O	-	<b>CT16B1_MAT0</b> — Match output 0 for 16-bit timer 1.
PIO1_10/AD6/CT16B1_MAT1	30[5]	no	I/O	I; PU	<b>PIO1_10</b> — General purpose digital input/output pin.
			I	-	<b>AD6</b> — A/D converter, input 6.
			O	-	<b>CT16B1_MAT1</b> — Match output 1 for 16-bit timer 1.
PIO1_11/AD7	42[5]	no	I/O	I; PU	<b>PIO1_11</b> — General purpose digital input/output pin.
			I	-	<b>AD7</b> — A/D converter, input 7.
PIO2_0 to PIO2_11					<b>Port 2</b> — Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block.
PIO2_0/DTR/SSEL1	2[3]	no	I/O	I; PU	<b>PIO2_0</b> — General purpose digital input/output pin.
			I/O	-	<b>DTR</b> — Data Terminal Ready output for UART.
			I/O	-	<b>SSEL1</b> — Slave Select for SPI1.
PIO2_1/DSR/SCK1	13[3]	no	I/O	I; PU	<b>PIO2_1</b> — General purpose digital input/output pin.
			I	-	<b>DSR</b> — Data Set Ready input for UART.
			I/O	-	<b>SCK1</b> — Serial clock for SPI1.
PIO2_2/DCD/MISO1	26[3]	no	I/O	I; PU	<b>PIO2_2</b> — General purpose digital input/output pin.
			I	-	<b>DCD</b> — Data Carrier Detect input for UART.
			I/O	-	<b>MISO1</b> — Master In Slave Out for SPI1.
PIO2_3/RI/MOSI1	38[3]	no	I/O	I; PU	<b>PIO2_3</b> — General purpose digital input/output pin.
			I	-	<b>RI</b> — Ring Indicator input for UART.
			I/O	-	<b>MOSI1</b> — Master Out Slave In for SPI1.
PIO2_4	18[3]	no	I/O	I; PU	<b>PIO2_4</b> — General purpose digital input/output pin.
PIO2_5	21[3]	no	I/O	I; PU	<b>PIO2_5</b> — General purpose digital input/output pin.
PIO2_6	1[3]	no	I/O	I; PU	<b>PIO2_6</b> — General purpose digital input/output pin.
PIO2_7	11[3]	no	I/O	I; PU	<b>PIO2_7</b> — General purpose digital input/output pin.
PIO2_8	12[3]	no	I/O	I; PU	<b>PIO2_8</b> — General purpose digital input/output pin.
PIO2_9	24[3]	no	I/O	I; PU	<b>PIO2_9</b> — General purpose digital input/output pin.
PIO2_10	25[3]	no	I/O	I; PU	<b>PIO2_10</b> — General purpose digital input/output pin.
PIO2_11/SCK0	31[3]	no	I/O	I; PU	<b>PIO2_11</b> — General purpose digital input/output pin.
			I/O	-	<b>SCK0</b> — Serial clock for SPI0.
PIO3_0 to PIO3_3					<b>Port 3</b> — Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_4 to PIO3_11 are not available.

Table 3. LPC11C12/C14 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO3_0/DTR	36[3]	no	I/O O	I; PU -	<b>PIO3_0</b> — General purpose digital input/output pin. <b>DTR</b> — Data Terminal Ready output for UART.
PIO3_1/DSR	37[3]	no	I/O I	I; PU -	<b>PIO3_1</b> — General purpose digital input/output pin. <b>DSR</b> — Data Set Ready input for UART.
PIO3_2/DCD	43[3]	no	I/O I	I; PU -	<b>PIO3_2</b> — General purpose digital input/output pin. <b>DCD</b> — Data Carrier Detect input for UART.
PIO3_3/RI	48[3]	no	I/O I	I; PU -	<b>PIO3_3</b> — General purpose digital input/output pin. <b>RI</b> — Ring Indicator input for UART.
CAN_RXD	19[6]	no	I	I; IA	<b>CAN_RXD</b> — C_CAN receive data input.
CAN_TXD	20[6]	no	O	I; IA	<b>CAN_TXD</b> — C_CAN transmit data output.
V <sub>DD</sub>	8; 44	-	I	-	Supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	6[7]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	7[7]	-	O	-	Output from the oscillator amplifier.
V <sub>SS</sub>	5; 41	-	I	-	Ground.

- [1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V<sub>DD</sub> level); IA = inactive, no pull-up/down enabled.
- [2] 5 V tolerant pad. **RESET** functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See [Figure 27](#) for the reset pad configuration.
- [3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see [Figure 26](#)).
- [4] I<sup>2</sup>C-bus pads compliant with the I<sup>2</sup>C-bus specification for I<sup>2</sup>C standard mode and I<sup>2</sup>C Fast-mode Plus.
- [5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see [Figure 26](#)).
- [6] 5 V tolerant digital I/O pad without pull-up/pull-down resistors.
- [7] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

Table 4. LPC11C22/C24 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO0_0 to PIO0_11					<b>Port 0</b> — Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.
RESET/PIO0_0	3[2]	yes	I	I; PU	<b>RESET</b> — External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
			I/O	-	<b>PIO0_0</b> — General purpose digital input/output pin with 10 ns glitch filter.

Table 4. LPC11C22/C24 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO0_1/CLKOUT/ CT32B0_MAT2	4[3]	yes	I/O	I; PU	<b>PIO0_1</b> — General purpose digital input/output pin. A LOW level on this pin during reset starts the flash ISP command handler via UART (if PIO0_3 is HIGH) or via C_CAN (if PIO0_3 is LOW).
			O	-	<b>CLKOUT</b> — Clockout pin.
			O	-	<b>CT32B0_MAT2</b> — Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0	10[3]	yes	I/O	I; PU	<b>PIO0_2</b> — General purpose digital input/output pin.
			I/O	-	<b>SSEL0</b> — Slave Select for SPI0.
			I	-	<b>CT16B0_CAP0</b> — Capture input 0 for 16-bit timer 0.
PIO0_3	14[3]	yes	I/O	I; PU	<b>PIO0_3</b> — General purpose digital input/output pin. This pin is monitored during reset: Together with a LOW level on pin PIO0_1, a LOW level starts the flash ISP command handler via C_CAN and a HIGH level starts the flash ISP command handler via UART.
			I/O	-	<b>SCL</b> — I <sup>2</sup> C-bus, open-drain clock input/output. High-current sink only if I <sup>2</sup> C Fast-mode Plus is selected in the I/O configuration register.
PIO0_4/SCL	15[4]	yes	I/O	I; IA	<b>PIO0_4</b> — General purpose digital input/output pin (open-drain).
			I/O	-	<b>SDA</b> — I <sup>2</sup> C-bus, open-drain data input/output. High-current sink only if I <sup>2</sup> C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	16[4]	yes	I/O	I; IA	<b>PIO0_5</b> — General purpose digital input/output pin (open-drain).
			I/O	-	<b>SCK0</b> — Serial clock for SPI0.
PIO0_6/SCK0	23[3]	yes	I/O	I; PU	<b>PIO0_6</b> — General purpose digital input/output pin.
			I/O	-	<b>CTS</b> — Clear To Send input for UART.
PIO0_7/ $\overline{\text{CTS}}$	24[3]	yes	I/O	I; PU	<b>PIO0_7</b> — General purpose digital input/output pin (high-current output driver).
			I	-	<b>CT16B0_MAT0</b> — Match output 0 for 16-bit timer 0.
			I/O	-	<b>MISO0</b> — Master In Slave Out for SPI0.
PIO0_8/MISO0/ CT16B0_MAT0	27[3]	yes	I/O	I; PU	<b>PIO0_8</b> — General purpose digital input/output pin.
			I/O	-	<b>MOSI0</b> — Master Out Slave In for SPI0.
			O	-	<b>CT16B0_MAT1</b> — Match output 1 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	28[3]	yes	I/O	I; PU	<b>PIO0_9</b> — General purpose digital input/output pin.
			I/O	-	<b>SWCLK</b> — Serial wire clock.
			O	-	<b>CT16B0_MAT2</b> — Match output 2 for 16-bit timer 0.
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	29[3]	yes	I	I; PU	<b>PIO0_10</b> — General purpose digital input/output pin.
			I/O	-	<b>SCK0</b> — Serial clock for SPI0.
			O	-	<b>CT32B0_MAT3</b> — Match output 3 for 32-bit timer 0.
R/PIO0_11/ AD0/ CT32B0_MAT3	32[5]	yes	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO0_11</b> — General purpose digital input/output pin.
			I	-	<b>AD0</b> — A/D converter, input 0.
PIO1_0 to PIO1_11			O	-	<b>CT32B0_MAT3</b> — Match output 3 for 32-bit timer 0.
			O	-	<b>Port 1</b> — Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.

Table 4. LPC11C22/C24 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
R/PIO1_0/AD1/ CT32B1_CAP0	33[5]	yes	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_0</b> — General purpose digital input/output pin.
			I	-	<b>AD1</b> — A/D converter, input 1.
			I	-	<b>CT32B1_CAP0</b> — Capture input 0 for 32-bit timer 1.
R/PIO1_1/AD2/ CT32B1_MAT0	34[5]	no	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_1</b> — General purpose digital input/output pin.
			I	-	<b>AD2</b> — A/D converter, input 2.
			O	-	<b>CT32B1_MAT0</b> — Match output 0 for 32-bit timer 1.
R/PIO1_2/AD3/ CT32B1_MAT1	35[5]	no	-	I; PU	<b>R</b> — Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	<b>PIO1_2</b> — General purpose digital input/output pin.
			I	-	<b>AD3</b> — A/D converter, input 3.
			O	-	<b>CT32B1_MAT1</b> — Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/ CT32B1_MAT2	39[5]	no	I/O	I; PU	<b>SWDIO</b> — Serial wire debug input/output.
			I/O	-	<b>PIO1_3</b> — General purpose digital input/output pin.
			I	-	<b>AD4</b> — A/D converter, input 4.
			O	-	<b>CT32B1_MAT2</b> — Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	no	I/O	I; PU	<b>PIO1_4</b> — General purpose digital input/output pin with 10 ns glitch filter.
			I	-	<b>AD5</b> — A/D converter, input 5.
			O	-	<b>CT32B1_MAT3</b> — Match output 3 for 32-bit timer 1.
			I	-	<b>WAKEUP</b> — Deep power-down mode wake-up pin with 20 ns glitch filter. This pin must be pulled HIGH externally to enter Deep power-down mode and pulled LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
PIO1_5/RTS/ CT32B0_CAP0	45[3]	no	I/O	I; PU	<b>PIO1_5</b> — General purpose digital input/output pin.
			O	-	<b>RTS</b> — Request To Send output for UART.
			I	-	<b>CT32B0_CAP0</b> — Capture input 0 for 32-bit timer 0.
PIO1_6/RXD/ CT32B0_MAT0	46[3]	no	I/O	I; PU	<b>PIO1_6</b> — General purpose digital input/output pin.
			I	-	<b>RXD</b> — Receiver input for UART.
			O	-	<b>CT32B0_MAT0</b> — Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	47[3]	no	I/O	I; PU	<b>PIO1_7</b> — General purpose digital input/output pin.
			O	-	<b>TXD</b> — Transmitter output for UART.
			O	-	<b>CT32B0_MAT1</b> — Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	9[3]	no	I/O	I; PU	<b>PIO1_8</b> — General purpose digital input/output pin.
			I	-	<b>CT16B1_CAP0</b> — Capture input 0 for 16-bit timer 1.
PIO1_10/AD6/ CT16B1_MAT1	30[5]	no	I/O	I; PU	<b>PIO1_10</b> — General purpose digital input/output pin.
			I	-	<b>AD6</b> — A/D converter, input 6.
			O	-	<b>CT16B1_MAT1</b> — Match output 1 for 16-bit timer 1.

Table 4. LPC11C22/C24 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
PIO1_11/AD7	42 <sup>[3]</sup>	no	I/O I	I; PU -	<b>PIO1_11</b> — General purpose digital input/output pin. <b>AD7</b> — A/D converter, input 7.
PIO2_0 to PIO2_11					<b>Port 2</b> — Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block.
PIO2_0/DTR/ SSEL1	2 <sup>[3]</sup>	no	I/O I/O I/O	I; PU - -	<b>PIO2_0</b> — General purpose digital input/output pin. <b>DTR</b> — Data Terminal Ready output for UART. <b>SSEL1</b> — Slave Select for SPI1.
PIO2_1/DSR/SCK1	13 <sup>[3]</sup>	no	I/O I I/O	I; PU - -	<b>PIO2_1</b> — General purpose digital input/output pin. <b>DSR</b> — Data Set Ready input for UART. <b>SCK1</b> — Serial clock for SPI1.
PIO2_2/DCD/ MISO1	26 <sup>[3]</sup>	no	I/O I I/O	I; PU - -	<b>PIO2_2</b> — General purpose digital input/output pin. <b>DCD</b> — Data Carrier Detect input for UART. <b>MISO1</b> — Master In Slave Out for SPI1.
PIO2_3/RI/MOSI1	38 <sup>[3]</sup>	no	I/O I I/O	I; PU - -	<b>PIO2_3</b> — General purpose digital input/output pin. <b>RI</b> — Ring Indicator input for UART. <b>MOSI1</b> — Master Out Slave In for SPI1.
PIO2_6	1 <sup>[3]</sup>	no	I/O	I; PU	<b>PIO2_6</b> — General purpose digital input/output pin.
PIO2_7	11 <sup>[3]</sup>	no	I/O	I; PU	<b>PIO2_7</b> — General purpose digital input/output pin.
PIO2_8	12 <sup>[3]</sup>	no	I/O	I; PU	<b>PIO2_8</b> — General purpose digital input/output pin.
PIO2_10	25 <sup>[3]</sup>	no	I/O	I; PU	<b>PIO2_10</b> — General purpose digital input/output pin.
PIO2_11/SCK0	31 <sup>[3]</sup>	no	I/O I/O	I; PU -	<b>PIO2_11</b> — General purpose digital input/output pin. <b>SCK0</b> — Serial clock for SPI0.
PIO3_0 to PIO3_3					<b>Port 3</b> — Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_4 to PIO3_11 are not available.
PIO3_0/DTR	36 <sup>[3]</sup>	no	I/O O	I; PU -	<b>PIO3_0</b> — General purpose digital input/output pin. <b>DTR</b> — Data Terminal Ready output for UART.
PIO3_1/DSR	37 <sup>[3]</sup>	no	I/O I	I; PU -	<b>PIO3_1</b> — General purpose digital input/output pin. <b>DSR</b> — Data Set Ready input for UART.
PIO3_2/DCD	43 <sup>[3]</sup>	no	I/O I	I; PU -	<b>PIO3_2</b> — General purpose digital input/output pin. <b>DCD</b> — Data Carrier Detect input for UART.
PIO3_3/RI	48 <sup>[3]</sup>	no	I/O I	I; PU -	<b>PIO3_3</b> — General purpose digital input/output pin. <b>RI</b> — Ring Indicator input for UART.
CANL	18	no	I/O	-	LOW-level CAN bus line.
CANH	19	no	I/O	-	HIGH-level CAN bus line.
STB	22	no	I	-	Silent mode control input for CAN transceiver (LOW = Normal mode, HIGH = silent mode).
VDD_CAN	17	-	-	-	Supply voltage for I/O level of CAN transceiver.
V <sub>CC</sub>	20	-	-	-	Supply voltage for CAN transceiver.

Table 4. LPC11C22/C24 pin description table

Symbol	Pin	Start logic inputs	Type	Reset state [1]	Description
GND	21	-	-	-	Ground for CAN transceiver.
V <sub>DD</sub>	8; 44	-	I	-	Supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	6[7]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	7[7]	-	O	-	Output from the oscillator amplifier.
V <sub>SS</sub>	5; 41	-	I	-	Ground.

- [1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V<sub>DD</sub> level); IA = inactive, no pull-up/down enabled.
- [2] 5 V tolerant pad.  $\overline{\text{RESET}}$  functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See [Figure 27](#) for the reset pad configuration.
- [3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see [Figure 26](#)).
- [4] I<sup>2</sup>C-bus pads compliant with the I<sup>2</sup>C-bus specification for I<sup>2</sup>C standard mode and I<sup>2</sup>C Fast-mode Plus.
- [5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see [Figure 26](#)).
- [6] 5 V tolerant digital I/O pad without pull-up/pull-down resistors.
- [7] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

## 7. Functional description

---

### 7.1 ARM Cortex-M0 processor

The ARM Cortex-M0 is a general purpose, 32-bit microprocessor, which offers high performance and very low power consumption.

### 7.2 On-chip flash program memory

The LPC11Cx2/Cx4 contain 32 kB (LPC11C14/C24) or 16 kB (LPC11C12/C22) of on-chip flash program memory.

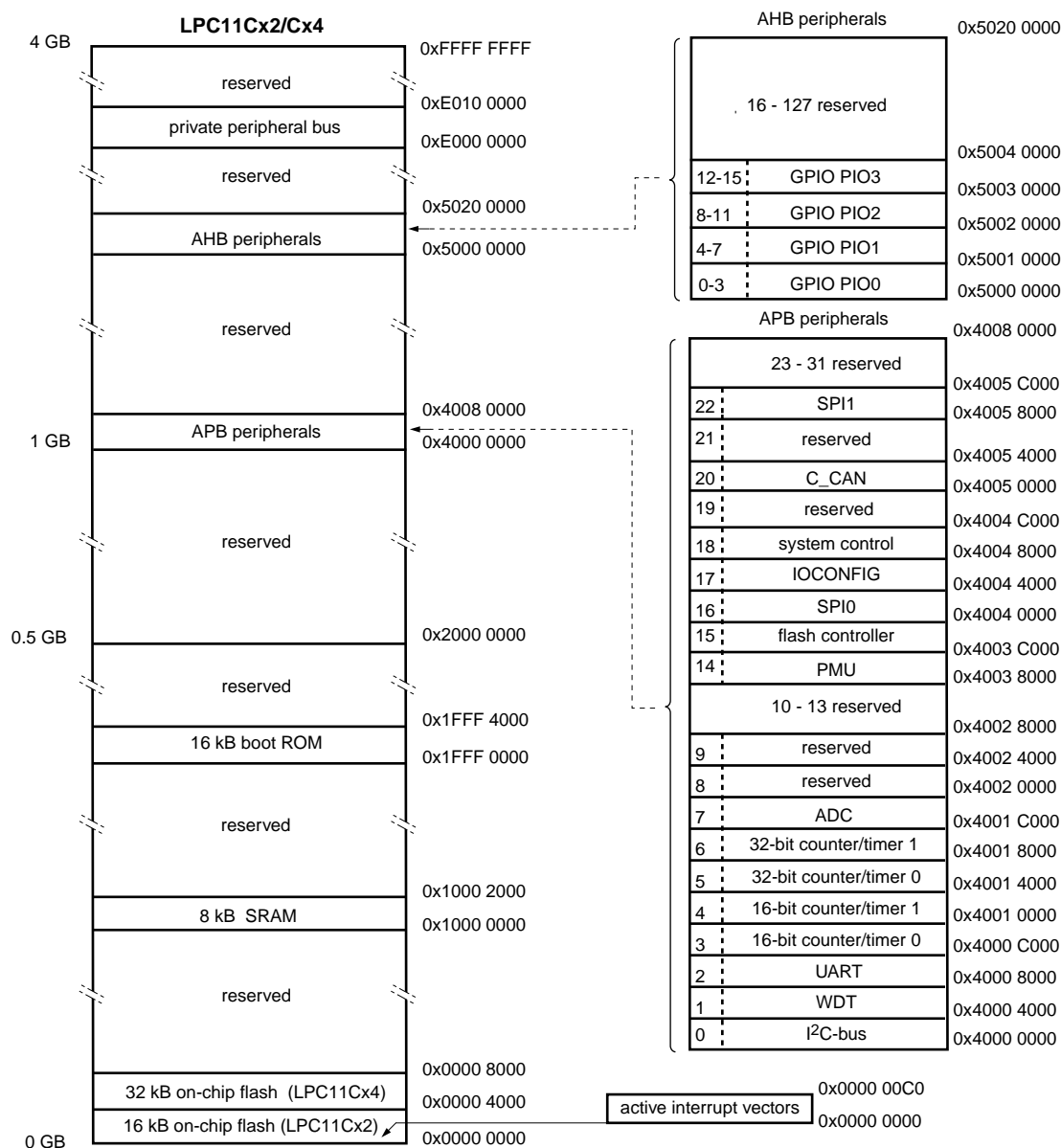
### 7.3 On-chip SRAM

The LPC11Cx2/Cx4 contain a total of 8 kB on-chip static RAM data memory.

### 7.4 Memory map

The LPC11Cx2/Cx4 incorporates several distinct memory regions, shown in the following figures. [Figure 4](#) shows the overall map of the entire address space from the user program viewpoint following reset. The interrupt vector area supports address remapping.

The AHB peripheral area is 2 megabyte in size, and is divided to allow for up to 128 peripherals. The APB peripheral area is 512 kB in size and is divided to allow for up to 32 peripherals. Each peripheral of either type is allocated 16 kilobytes of space. This allows simplifying the address decoding for each peripheral.



002aaf268

**Fig 4. LPC11Cx2/Cx4 memory map**

## 7.5 Nested Vectored Interrupt Controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is an integral part of the Cortex-M0. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

### 7.5.1 Features

- Controls system exceptions and peripheral interrupts.
- In the LPC11Cx2/Cx4, the NVIC supports 32 vectored interrupts including 13 inputs to the start logic from individual GPIO pins.



- Four programmable interrupt priority levels, with hardware priority level masking.
- Software interrupt generation.

### 7.5.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

Any GPIO pin (total of 40 pins (LPC11C12/C14) or 36 pins (LPC11C22/C24)) regardless of the selected function, can be programmed to generate an interrupt on a level, or rising edge or falling edge, or both.

### 7.6 IOCONFIG block

The IOCONFIG block allows selected pins of the microcontroller to have more than one function. Configuration registers control the multiplexers to allow connection between the pin and the on-chip peripherals.

Peripherals should be connected to the appropriate pins prior to being activated and prior to any related interrupt(s) being enabled. Activity of any enabled peripheral function that is not mapped to a related pin should be considered undefined.

### 7.7 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Multiple outputs can be set or cleared in one write operation.

LPC11Cx2/Cx4 use accelerated GPIO functions:

- GPIO registers are a dedicated AHB peripheral so that the fastest possible I/O timing can be achieved.
- Entire port value can be written in one instruction.

Additionally, any GPIO pin (total of 40 pins (LPC11C12/C14) or 36 pins (LPC11C22/C24)) providing a digital function can be programmed to generate an interrupt on a level, a rising or falling edge, or both.

#### 7.7.1 Features

- Bit level port registers allow a single instruction to set or clear any number of bits in one write operation.
- Direction control of individual bits.
- All GPIO pins default to inputs with pull-ups enabled after reset except for the I<sup>2</sup>C-bus true open-drain pins PIO0\_4 and PIO0\_5.
- Pull-up/pull-down resistor configuration can be programmed through the IOCONFIG block for each GPIO pin (except PIO0\_4 and PIO0\_5).
- All GPIO pins (except PIO0\_4 and PIO0\_5) are pulled up to 3.3 V ( $V_{DD} = 3.3$  V) if their pull-up resistor is enabled in the IOCONFIG block.

## 7.8 UART

The LPC11Cx2/Cx4 contain one UART.

Support for RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The UART includes a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

### 7.8.1 Features

- Maximum UART data bit rate of 3.125 Mbit/s.
- 16 Byte Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.

## 7.9 SPI serial I/O controller

The LPC11Cx2/Cx4 contain two SPI controllers. Both SPI controllers support SSP features.

The SPI controller is capable of operation on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SPI supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

### 7.9.1 Features

- Maximum SPI speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses
- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

## 7.10 I<sup>2</sup>C-bus serial I/O controller

The LPC11Cx2/Cx4 contain one I<sup>2</sup>C-bus controller.

The I<sup>2</sup>C-bus is bidirectional for inter-IC control using only two wires: a Serial CLock line (SCL) and a Serial DATA line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I<sup>2</sup>C is a multi-master bus and can be controlled by more than one bus master connected to it.

### 7.10.1 Features

- The I<sup>2</sup>C-interface is a standard I<sup>2</sup>C-bus compliant interface with open-drain pins. The I<sup>2</sup>C-bus interface also supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I<sup>2</sup>C-bus can be used for test and diagnostic purposes.
- The I<sup>2</sup>C-bus controller supports multiple address recognition and a bus monitor mode.

## 7.11 C\_CAN controller

Controller Area Network (CAN) is the definition of a high performance communication protocol for serial data communication. The C\_CAN controller is designed to provide a full implementation of the CAN protocol according to the CAN Specification Version 2.0B. The C\_CAN controller allows to build powerful local networks with low-cost multiplex wiring by supporting distributed real-time control with a very high level of security.

On-chip C\_CAN drivers provide an API for initialization and communication using CAN and CANopen standards.

### 7.11.1 Features

- Conforms to protocol version 2.0 parts A and B.
- Supports bit rate of up to 1 Mbit/s.
- Supports 32 Message Objects.
- Each Message Object has its own identifier mask.
- Provides programmable FIFO mode (concatenation of Message Objects).
- Provides maskable interrupts.
- Supports Disabled Automatic Retransmission (DAR) mode for time-triggered CAN applications.
- Provides programmable loop-back mode for self-test operation.

- The C\_CAN API includes the following functions:
  - C\_CAN set-up and initialization
  - C\_CAN send and receive messages
  - C\_CAN status
  - CANopen object dictionary
  - CANopen SDO expedited communication
  - CANopen SDO segmented communication primitives
  - CANopen SDO fall-back handler
- Flash ISP programming via C\_CAN supported.

### 7.11.2 On-chip, high-speed CAN transceiver

**Remark:** The on-chip CAN transceiver is available on parts LPC11C22/C24 only. Compared to the LPC11C12/C14, the LPC11C22/C24 supports fewer GPIO functions, and in addition, one counter/timer match function is removed to allow interfacing the CAN high-speed transceiver to the CAN bus. See [Table 4](#) and [Figure 1](#).

#### 7.11.2.1 Features

- Data rates of up to 1 Mbit/s
- Fully ISO 11898-2 compliant
- Undervoltage detection and thermal protection
- Low ElectroMagnetic Emission (EME) and high ElectroMagnetic Immunity (EMI)

#### 7.11.2.2 Normal mode

A LOW level on pin STB selects Normal mode. In this mode, the transceiver is able to transmit and receive data via the bus lines CANH and CANL (see [Figure 29](#)). The differential receiver converts the analog data on the bus lines into digital data which are received by the CAN\_RXD input of the C\_CAN controller.

#### 7.11.2.3 Silent mode

A HIGH level on pin STB selects Silent mode. In Silent mode the transmitter is disabled, releasing the bus pins to recessive state. All other functions, including the receiver, continue to operate as in Normal mode. Silent mode can be used to prevent a faulty C\_CAN controller from disrupting all network communications.

#### 7.11.2.4 Undervoltage protection

Should  $V_{CC}$  or  $VDD\_CAN$  drop below their respective undervoltage detection levels ( $V_{uvd(VCC)}$  and  $V_{uvd(VDD\_CAN)}$ ; see [Table 8](#)), the transceiver will switch off and disengage from the bus (zero load) until  $V_{CC}$  and  $VDD\_CAN$  have recovered.

#### 7.11.2.5 Thermal protection

The output drivers are protected against overtemperature conditions. If the virtual junction temperature exceeds the shutdown junction temperature,  $T_{j(sd)}$  (see [Table 8](#)), the output drivers will be disabled until the virtual junction temperature falls below  $T_{j(sd)}$ .

#### 7.11.2.6 Time-out function

A 'TXD dominant time-out' timer is started when the CAN\_TXD signal of the C\_CAN controller is set LOW. If the LOW state on the CAN\_TXD signal persists for longer than  $t_{to(dom)TXD}$ , the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when the CAN\_TXD signal is set HIGH. The TXD dominant time-out time also defines the minimum possible bit rate of 40 kbit/s.

### 7.12 10-bit ADC

The LPC11Cx2/Cx4 contains one ADC. The ADC is a single 10-bit successive approximation ADC with eight channels.

#### 7.12.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to  $V_{DD}$ .
- 10-bit conversion time  $\geq 2.44 \mu s$  (up to 400 kSamples/s).
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition of input pin or timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

### 7.13 General purpose external event counter/timers

The LPC11Cx2/Cx4 includes two 32-bit counter/timers and two 16-bit counter/timers. The counter/timer is designed to count cycles of the system derived clock. It can optionally generate interrupts or perform other actions at specified timer values, based on four match registers. Each counter/timer also includes one capture input to trap the timer value when an input signal transitions, optionally generating an interrupt.

#### 7.13.1 Features

- A 32-bit/16-bit timer/counter with a programmable 32-bit/16-bit prescaler.
- Counter or timer operation.
- One capture channel per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event may also generate an interrupt.
- Four match registers per timer that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.

- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.

## 7.14 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

## 7.15 Watchdog timer

The purpose of the watchdog is to reset the microcontroller within a selectable time period.

### 7.15.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect/Incomplete feed sequence causes reset/interrupt if enabled.
- Flag to indicate watchdog reset.
- Programmable 24-bit timer with internal prescaler.
- Selectable time period from  $(T_{cy(WDCLK)} \times 256 \times 4)$  to  $(T_{cy(WDCLK)} \times 2^{24} \times 4)$  in multiples of  $T_{cy(WDCLK)} \times 4$ .
- The Watchdog Clock (WDCLK) source can be selected from the Internal RC oscillator (IRC), the Watchdog oscillator, or the main clock. This gives a wide range of potential timing choices of Watchdog operation under different power reduction conditions. It also provides the ability to run the WDT from an entirely internal source that is not dependent on an external crystal and its associated components and wiring for increased reliability.

## 7.16 Clocking and power control

### 7.16.1 Crystal oscillators

The LPC11Cx2/Cx4 include three independent oscillators. These are the system oscillator, the Internal RC oscillator (IRC), and the Watchdog oscillator. Each oscillator can be used for more than one purpose as required in a particular application.

Following reset, the LPC11Cx2/Cx4 will operate from the Internal RC oscillator until switched by software. This allows systems to operate without any external crystal and the bootloader code to operate at a known frequency.

See [Figure 5](#) for an overview of the LPC11Cx2/Cx4 clock generation.

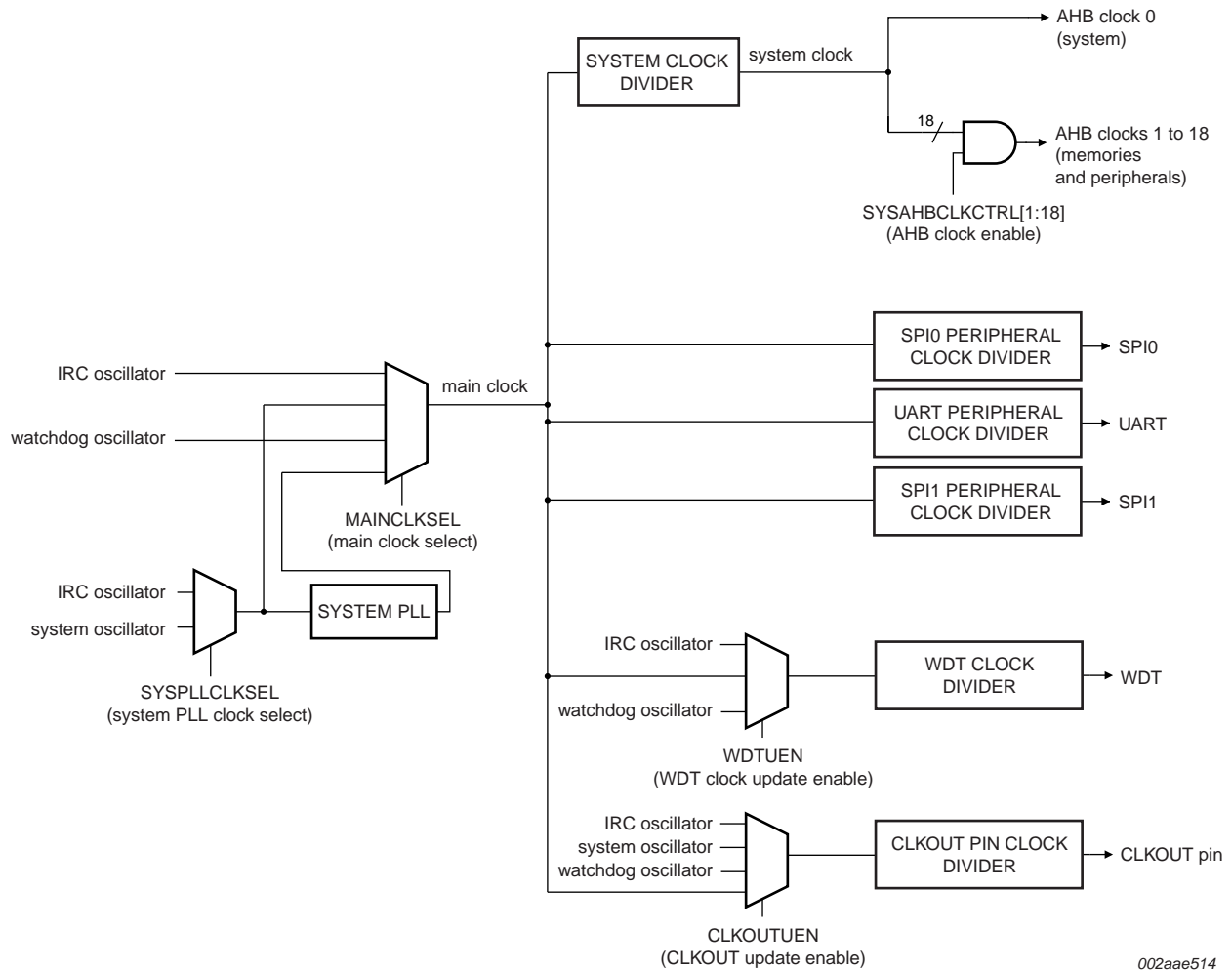


Fig 5. LPC11Cx2/Cx4 clock generation block diagram

#### 7.16.1.1 Internal RC oscillator

The IRC may be used as the clock source for the WDT, and/or as the clock that drives the PLL and subsequently the CPU. The nominal IRC frequency is 12 MHz. The IRC is trimmed to 1 % accuracy over the entire voltage and temperature range.

Upon power-up or any chip reset, the LPC11Cx2/Cx4 use the IRC as the clock source. Software may later switch to one of the other available clock sources.

#### 7.16.1.2 System oscillator

The system oscillator can be used as the clock source for the CPU, with or without using the PLL.

The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL.

#### 7.16.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 7.8 kHz and 1.7 MHz. The frequency spread over processing and temperature is  $\pm 40\%$  (see [Table 16](#)).

#### 7.16.2 System PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider may be set to divide by 2, 4, 8, or 16 to produce the output clock. The PLL output frequency must be lower than 100 MHz. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100  $\mu$ s.

#### 7.16.3 Clock output

The LPC11Cx2/Cx4 features a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

#### 7.16.4 Wake-up process

The LPC11Cx2/Cx4 begin operation at power-up and when awakened from Deep power-down mode by using the 12 MHz IRC oscillator as the clock source. This allows chip operation to resume quickly. If the system oscillator or the PLL is needed by the application, software will need to enable these features and wait for them to stabilize before they are used as a clock source.

#### 7.16.5 Power control

The LPC11Cx2/Cx4 support a variety of power control features. There are three special modes of processor power reduction: Sleep mode, Deep-sleep mode, and Deep power-down mode. The CPU clock rate may also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals, allowing fine tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Selected peripherals have their own clock divider which provides even better power control.

##### 7.16.5.1 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

In Sleep mode, execution of instructions is suspended until either a reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and may generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, memory systems and related controllers, and internal buses.



#### 7.16.5.2 Deep-sleep mode

In Deep-sleep mode, the chip is in Sleep mode, and in addition all analog blocks are shut down. As an exception, the user has the option to keep the watchdog oscillator and the BOD circuit running for self-timed wake-up and BOD protection. Deep-sleep mode allows for additional power savings.

Up to 13 pins total, see [Table 3](#), serve as external wake-up pins to a dedicated start logic to wake up the chip from Deep-sleep mode.

Unless the watchdog oscillator is selected to run in Deep-sleep mode, the clock source should be switched to IRC before entering Deep-sleep mode, because the IRC can be switched on and off glitch-free.

#### 7.16.5.3 Deep power-down mode

In Deep power-down mode, power is shut off to the entire chip with the exception of the WAKEUP pin. The LPC11Cx2/Cx4 can wake up from Deep power-down mode via the WAKEUP pin.

When entering Deep power-down mode, an external pull-up resistor is required on the WAKEUP pin to hold it HIGH. The  $\overline{\text{RESET}}$  pin must also be held HIGH to prevent it from floating while in Deep power-down mode.

### 7.17 System control

#### 7.17.1 Start logic

The start logic connects external pins to corresponding interrupts in the NVIC. Each pin shown in [Table 3](#) as input to the start logic has an individual interrupt in the NVIC interrupt vector table. The start logic pins can serve as external interrupt pins when the chip is running. In addition, an input signal on the start logic pins can wake up the chip from Deep-sleep mode when all clocks are shut down.

The start logic must be configured in the system configuration block and in the NVIC before being used.

#### 7.17.2 Reset

Reset has four sources on the LPC11Cx2/Cx4: the  $\overline{\text{RESET}}$  pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The  $\overline{\text{RESET}}$  pin is a Schmitt trigger input pin. Assertion of chip reset by any source, once the operating voltage attains a usable level, starts the IRC and initializes the flash controller.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the boot block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

An external pull-up resistor is required on the  $\overline{\text{RESET}}$  pin if Deep power-down mode is used.

### 7.17.3 Brownout detection

The LPC11Cx2/Cx4 includes four levels for monitoring the voltage on the  $V_{DD}$  pin. If this voltage falls below one of the four selected levels, the BOD asserts an interrupt signal to the NVIC. This signal can be enabled for interrupt in the Interrupt Enable Register in the NVIC in order to cause a CPU interrupt; if not, software can monitor the signal by reading a dedicated status register. Four additional threshold levels can be selected to cause a forced reset of the chip.

### 7.17.4 Code security (Code Read Protection - CRP)

This feature of the LPC11Cx2/Cx4 allows user to enable different levels of security in the system so that access to the on-chip flash and use of the Serial Wire Debugger (SWD) and In-System Programming (ISP) can be restricted. When needed, CRP is invoked by programming a specific pattern into a dedicated flash location. IAP commands are not affected by the CRP.

In addition, ISP entry via the PIO0\_1 pin can be disabled without enabling CRP. For details see the *LPC11Cx user manual*.

There are three levels of Code Read Protection:

1. CRP1 disables access to the chip via the SWD and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors can not be erased.
2. CRP2 disables access to the chip via the SWD and only allows full flash erase and update using a reduced set of the ISP commands.
3. Running an application with level CRP3 selected fully disables any access to the chip via the SWD pins and the ISP. This mode effectively disables ISP override using PIO0\_1 pin, too. It is up to the user's application to provide (if needed) flash update mechanism using IAP calls or call reinvoke ISP command to enable flash update via the UART.

#### CAUTION



If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

In addition to the three CRP levels, sampling of pin PIO0\_1 for valid user code can be disabled. For details see the *LPC11Cx user manual*.

### 7.17.5 Bootloader

The bootloader controls initial operation after reset and also provides the means to program the flash memory. This could be initial programming of a blank device, erasure and re-programming of a previously programmed device, or programming of the flash memory by the application program in a running system.

The bootloader code is executed every time the part is reset or powered up. The loader can either execute the user application code or the ISP command handler via UART or C\_CAN. A LOW level during reset applied to the PIO0\_1 pin is considered as an external hardware request to start the ISP command handler. The state of PIO0\_3 at reset determines whether the UART (PIO0\_3 HIGH) or the C\_CAN (PIO0\_3 LOW) interface will be used.

The C\_CAN ISP command handler uses the CANopen protocol and data organization method. C\_CAN ISP commands have the same functionality as UART ISP commands.

### 7.17.6 APB interface

The APB peripherals are located on one APB bus.

### 7.17.7 AHBLite

The AHBLite connects the CPU bus of the ARM Cortex-M0 to the flash memory, the main static RAM, and the Boot ROM.

### 7.17.8 External interrupt inputs

All GPIO pins can be level or edge sensitive interrupt inputs. In addition, start logic inputs serve as external interrupts (see [Section 7.17.1](#)).

## 7.18 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug with four breakpoints and two watchpoints is supported.

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).<sup>[1]</sup>

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DD</sub>	supply voltage (core and external rail)	on pins V <sub>DD</sub>	<sup>[2]</sup> -0.5	4.6	V
V <sub>I</sub>	input voltage	5 V tolerant I/O pins; V <sub>DD</sub> ≥ 1.8 V	<sup>[3]</sup> -0.5	+5.5	V
V <sub>x</sub>	voltage on pin x	no time limit; DC value			
		on pins CANH and CANL	-58	+58	V
		on pins STB, V <sub>CC</sub> , VDD_CAN	-0.3	+7	V
I <sub>DD</sub>	supply current	per supply pin	<sup>[4]</sup> -	100	mA
I <sub>SS</sub>	ground current	per ground pin	<sup>[4]</sup> -	100	mA
I <sub>latch</sub>	I/O latch-up current	-(0.5V <sub>DD</sub> ) < V <sub>I</sub> < (1.5V <sub>DD</sub> ); T <sub>j</sub> < 125 °C	-	100	mA
T <sub>stg</sub>	storage temperature	non-operating	<sup>[5]</sup> -65	+150	°C
T <sub>j(max)</sub>	maximum junction temperature		-	150	°C
P <sub>tot(pack)</sub>	total power dissipation (per package)	based on package heat transfer, not device power consumption	-	1.5	W
V <sub>ESD</sub>	electrostatic discharge voltage	human body model; all pins except CAN on-chip transceiver pins CANL, CANH, STB, VDD_CAN, V <sub>CC</sub> , GND on LPC11C22/C24	<sup>[6]</sup> -6500	+6500	V
		pins CANH and CANL on LPC11C22/C24	<sup>[6]</sup> -8000	+8000	V
		pins STB, VDD_CAN, V <sub>CC</sub> , GND on LPC11C22/C24	<sup>[6]</sup> -4000	+4000	V

[1] The following applies to the limiting values:

- a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.
- b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V<sub>SS</sub> unless otherwise noted.

[2] Maximum/minimum voltage above the maximum operating voltage (see Table 6) and below ground that can be applied for a short time (<10 ms) to a device without leading to irrecoverable failure. Failure includes the loss of reliability and shorter lifetime of the device.

[3] Including voltage on outputs in 3-state mode.

[4] The peak current is limited to 25 times the corresponding maximum current.

[5] The maximum non-operating storage temperature is different than the temperature for required shelf life which should be determined based on required shelf lifetime. Please refer to the JEDEC spec (J-STD-033B.1) for further details.

[6] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

## 9. Static characteristics

**Table 6. Static characteristics**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$V_{DD}$	supply voltage (core and external rail)	on pins $V_{DD}$	1.8	3.3	3.6	V
$I_{DD}$	supply current	Active mode; code <code>while(1){}</code> executed from flash				
		system clock = 12 MHz $V_{DD} = 3.3\text{ V}$	<a href="#">[2]</a> <a href="#">[3]</a> <a href="#">[4]</a> <a href="#">[5]</a> <a href="#">[6]</a> <a href="#">[7]</a> -	3	-	mA
		system clock = 50 MHz $V_{DD} = 3.3\text{ V}$	<a href="#">[2]</a> <a href="#">[3]</a> <a href="#">[6]</a> <a href="#">[5]</a> <a href="#">[7]</a> <a href="#">[8]</a> -	9	-	mA
		Sleep mode; system clock = 12 MHz $V_{DD} = 3.3\text{ V}$	<a href="#">[2]</a> <a href="#">[3]</a> <a href="#">[4]</a> <a href="#">[5]</a> <a href="#">[6]</a> <a href="#">[7]</a> -	2	-	mA
		Deep-sleep mode; $V_{DD} = 3.3\text{ V}$	<a href="#">[2]</a> <a href="#">[3]</a> <a href="#">[5]</a> <a href="#">[9]</a> -	6	-	$\mu\text{A}$
		Deep power-down mode; $V_{DD} = 3.3\text{ V}$	<a href="#">[2]</a> <a href="#">[10]</a> -	220	-	nA
<b>Standard port pins, RESET</b>						
$I_{IL}$	LOW-level input current	$V_I = 0\text{ V}$ ; on-chip pull-up resistor disabled	-	0.5	10	nA
$I_{IH}$	HIGH-level input current	$V_I = V_{DD}$ ; on-chip pull-down resistor disabled	-	0.5	10	nA
$I_{OZ}$	OFF-state output current	$V_O = 0\text{ V}$ ; $V_O = V_{DD}$ ; on-chip pull-up/down resistors disabled	-	0.5	10	nA
$V_I$	input voltage	$V_{DD} \geq 1.8\text{ V}$	<a href="#">[11]</a> <a href="#">[12]</a> 0	-	5.0	V
		$V_{DD} = 0\text{ V}$	0	-	3.6	V
$V_O$	output voltage	output active	0	-	$V_{DD}$	V
$V_{IH}$	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	$0.3V_{DD}$	V
$V_{hys}$	hysteresis voltage		-	0.4	-	V
$V_{OH}$	HIGH-level output voltage	$2.0\text{ V} \leq V_{DD} \leq 3.6\text{ V}$ ; $I_{OH} = -4\text{ mA}$	$V_{DD} - 0.4$	-	-	V
		$1.8\text{ V} \leq V_{DD} < 2.0\text{ V}$ ; $I_{OH} = -3\text{ mA}$	$V_{DD} - 0.4$	-	-	V

**Table 6. Static characteristics ...continued** $T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
V <sub>OL</sub>	LOW-level output voltage	2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V; I <sub>OL</sub> = 4 mA	-	-	0.4	V
		1.8 V ≤ V <sub>DD</sub> < 2.0 V; I <sub>OL</sub> = 3 mA	-	-	0.4	V
I <sub>OH</sub>	HIGH-level output current	V <sub>OH</sub> = V <sub>DD</sub> − 0.4 V; 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	−4	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	−3	-	-	mA
I <sub>OL</sub>	LOW-level output current	V <sub>OL</sub> = 0.4 V 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	3	-	-	mA
I <sub>OHS</sub>	HIGH-level short-circuit output current	V <sub>OH</sub> = 0 V	<sup>[13]</sup> -	-	−45	mA
I <sub>OLS</sub>	LOW-level short-circuit output current	V <sub>OL</sub> = V <sub>DD</sub>	<sup>[13]</sup> -	-	50	mA
I <sub>pd</sub>	pull-down current	V <sub>I</sub> = 5 V	10	50	150	μA
I <sub>pu</sub>	pull-up current	V <sub>I</sub> = 0 V; 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	−10	−50	−85	μA
		V <sub>DD</sub> < V <sub>I</sub> < 5 V	0	0	0	μA
High-drive output pin (PIO0_7)						
I <sub>IL</sub>	LOW-level input current	V <sub>I</sub> = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I <sub>IH</sub>	HIGH-level input current	V <sub>I</sub> = V <sub>DD</sub> ; on-chip pull-down resistor disabled	-	0.5	10	nA
I <sub>OZ</sub>	OFF-state output current	V <sub>O</sub> = 0 V; V <sub>O</sub> = V <sub>DD</sub> ; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V <sub>I</sub>	input voltage	V <sub>DD</sub> ≥ 1.8 V	<sup>[11]</sup> 0 <sup>[12]</sup>	-	5.0	V
		V <sub>DD</sub> = 0 V	0	-	3.6	V
V <sub>O</sub>	output voltage	output active	0	-	V <sub>DD</sub>	V
V <sub>IH</sub>	HIGH-level input voltage		0.7V <sub>DD</sub>	-	-	V
V <sub>IL</sub>	LOW-level input voltage		-	-	0.3V <sub>DD</sub>	V
V <sub>hys</sub>	hysteresis voltage		0.4	-	-	V
V <sub>OH</sub>	HIGH-level output voltage	2.5 V ≤ V <sub>DD</sub> ≤ 3.6 V; I <sub>OH</sub> = −20 mA	V <sub>DD</sub> − 0.4	-	-	V
		1.8 V ≤ V <sub>DD</sub> < 2.5 V; I <sub>OH</sub> = −12 mA	V <sub>DD</sub> − 0.4	-	-	V

**Table 6. Static characteristics ...continued**  
 $T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
V <sub>OL</sub>	LOW-level output voltage	2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V; I <sub>OL</sub> = 4 mA	-	-	0.4	V
		1.8 V ≤ V <sub>DD</sub> < 2.0 V; I <sub>OL</sub> = 3 mA	-	-	0.4	V
I <sub>OH</sub>	HIGH-level output current	V <sub>OH</sub> = V <sub>DD</sub> − 0.4 V; 2.5 V ≤ V <sub>DD</sub> ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.5 V	12	-	-	mA
I <sub>OL</sub>	LOW-level output current	V <sub>OL</sub> = 0.4 V 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	3	-	-	mA
I <sub>OLS</sub>	LOW-level short-circuit output current	V <sub>OL</sub> = V <sub>DD</sub>	<sup>[13]</sup> -	-	50	mA
I <sub>pd</sub>	pull-down current	V <sub>I</sub> = 5 V	10	50	150	μA
I <sub>pu</sub>	pull-up current	V <sub>I</sub> = 0 V 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	−10	−50	−85	μA
		V <sub>DD</sub> < V <sub>I</sub> < 5 V	0	0	0	μA
I <sup>2</sup> C-bus pins (PIO0_4 and PIO0_5)						
V <sub>IH</sub>	HIGH-level input voltage		0.7V <sub>DD</sub>	-	-	V
V <sub>IL</sub>	LOW-level input voltage		-	-	0.3V <sub>DD</sub>	V
V <sub>hys</sub>	hysteresis voltage		-	0.05V <sub>DD</sub>	-	V
I <sub>OL</sub>	LOW-level output current	V <sub>OL</sub> = 0.4 V; I <sup>2</sup> C-bus pins configured as standard mode pins 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	3.5	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	3	-	-	
I <sub>OL</sub>	LOW-level output current	V <sub>OL</sub> = 0.4 V; I <sup>2</sup> C-bus pins configured as Fast-mode Plus pins 2.0 V ≤ V <sub>DD</sub> ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V <sub>DD</sub> < 2.0 V	16	-	-	
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>DD</sub>	<sup>[14]</sup> -	2	4	μA
		V <sub>I</sub> = 5 V	-	10	22	μA
Oscillator pins						
V <sub>i(xtal)</sub>	crystal input voltage		−0.5	1.8	1.95	V
V <sub>o(xtal)</sub>	crystal output voltage		−0.5	1.8	1.95	V

- [1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.  
 [2]  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .  
 [3]  $I_{DD}$  measurements were performed with all pins configured as GPIO outputs driven LOW and pull-up resistors disabled.  
 [4] IRC enabled; system oscillator disabled; system PLL disabled.

- [5] Pin CAN\_RXD pulled LOW externally.
- [6] BOD disabled.
- [7] All peripherals disabled in the SYSAHBCLKCTRL register. Peripheral clocks to UART and SPI0/1 disabled in system configuration block.
- [8] IRC disabled; system oscillator enabled; system PLL enabled.
- [9] All oscillators and analog blocks turned off in the PDSLEEPCFG register; PDSLEEPCFG = 0x0000 18FF.
- [10] WAKEUP pin pulled HIGH externally.
- [11] Including voltage on outputs in 3-state mode.
- [12] 3-state outputs go into 3-state mode in Deep power-down mode.
- [13] Allowed as long as the current limit does not exceed the maximum current allowed by the device.
- [14] To  $V_{SS}$ .

## 9.1 ADC characteristics

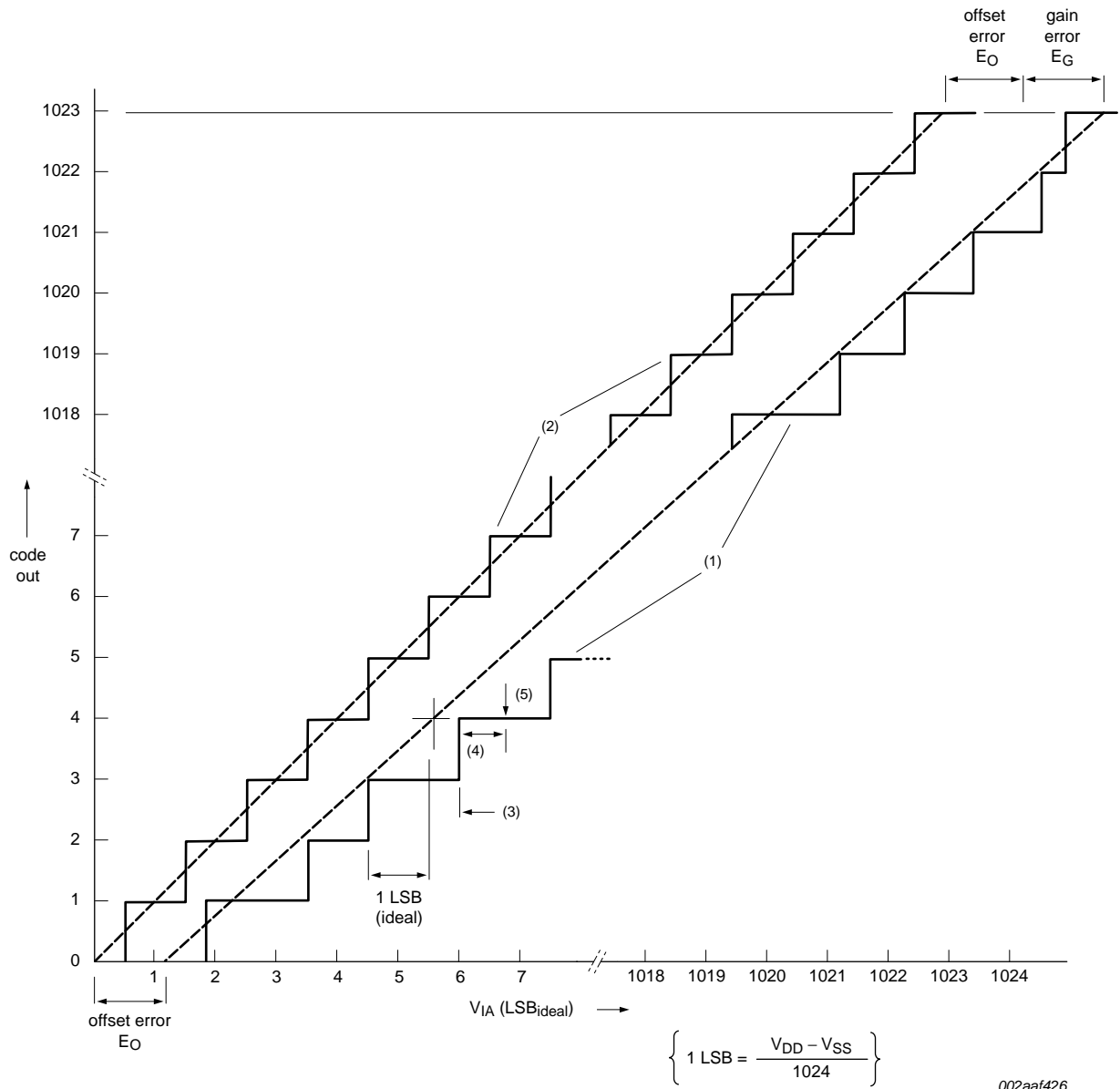
**Table 7. ADC static characteristics**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  unless otherwise specified; ADC frequency 4.5 MHz,  $V_{DD} = 2.5\text{ V}$  to  $3.6\text{ V}$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IA}$	analog input voltage		0	-	$V_{DD}$	V
$C_{ia}$	analog input capacitance		-	-	1	pF
$E_D$	differential linearity error	[1][2]	-	-	$\pm 1$	LSB
$E_{L(adj)}$	integral non-linearity	[3]	-	-	$\pm 1.5$	LSB
$E_O$	offset error	[4]	-	-	$\pm 3.5$	LSB
$E_G$	gain error	[5]	-	-	0.6	%
$E_T$	absolute error	[6]	-	-	$\pm 4$	LSB
$R_{vsi}$	voltage source interface resistance		-	-	40	k $\Omega$
$R_i$	input resistance	[7][8]	-	-	2.5	M $\Omega$

- [1] The ADC is monotonic, there are no missing codes.
- [2] The differential linearity error ( $E_D$ ) is the difference between the actual step width and the ideal step width. See [Figure 6](#).
- [3] The integral non-linearity ( $E_{L(adj)}$ ) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See [Figure 6](#).
- [4] The offset error ( $E_O$ ) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See [Figure 6](#).
- [5] The gain error ( $E_G$ ) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See [Figure 6](#).
- [6] The absolute error ( $E_T$ ) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See [Figure 6](#).
- [7]  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; maximum sampling frequency  $f_s = 400\text{ kSamples/s}$  and analog input capacitance  $C_{ia} = 1\text{ pF}$ .
- [8] Input resistance  $R_i$  depends on the sampling frequency  $f_s$ :  $R_i = 1 / (f_s \times C_{ia})$ .





- (1) Example of an actual transfer curve.
- (2) The ideal transfer curve.
- (3) Differential linearity error ( $E_D$ ).
- (4) Integral non-linearity ( $E_{L(adj)}$ ).
- (5) Center of a step of the actual transfer curve.

**Fig 6. ADC characteristics**

## 9.2 C\_CAN on-chip, high-speed transceiver characteristics

**Table 8. Static characteristics**

$T_{amb} = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ;  $V_{CC} = 4.5\text{ V}$  to  $5.5\text{ V}$ ;  $R_L = 60\ \Omega$ ; unless otherwise specified; all voltages are defined with respect to ground; positive currents flow into the IC. Also see [Figure 29](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Supply; pin VCC</b>						
$V_{CC}$	supply voltage		4.5	-	5.5	V
$I_{CC}$	supply current	Silent mode	0.1	1	2.5	mA
		Normal mode				
		recessive	2.5	5	10	mA
		dominant; CAN_TXD = LOW	20	50	70	mA
$V_{uvd}(V_{CC})$	undervoltage detection voltage on pin $V_{CC}$		3.5	-	4.5	V
<b>I/O level adapter supply; pin VDD_CAN</b>						
$V_{DD}$	supply voltage	on pin VDD_CAN	<a href="#">[1]</a> 2.8	-	5.5	V
$I_{DD}$	supply current	on pin VDD_CAN; Normal and Silent modes				
		recessive; CAN_TXD = HIGH	10	80	250	$\mu\text{A}$
		dominant; CAN_TXD = LOW	50	350	500	$\mu\text{A}$
$V_{uvd}(V_{DD\_CAN})$	undervoltage detection voltage on pin VDD_CAN		1.3	-	2.7	V
<b>Mode control input; pin STB</b>						
$V_{IH}$	HIGH-level input voltage		$0.7V_{CC}$	-	$V_{CC} + 0.3$	V
$V_{IL}$	LOW-level input voltage		-0.3	-	$0.3V_{CC}$	V
$I_{IH}$	HIGH-level input current		1	4	10	$\mu\text{A}$
$I_{IL}$	LOW-level input current	Voltage on pin STB = 0 V	-1	0	+1	$\mu\text{A}$
<b>Bus lines; pins CANH and CANL</b>						
$V_{O(dom)}$	dominant output voltage	CAN_TXD = LOW; $t < t_{to(dom)TXD}$				
		pin CANH	2.75	3.5	4.5	V
		pin CANL	0.5	1.5	2.25	V
$V_{dom(TX)sym}$	transmitter dominant voltage symmetry	$V_{dom(TX)sym} = V_{CC} - V_{CANH} - V_{CANL}$	-400	0	+400	mV
$V_{O(dif)bus}$	bus differential output voltage	CAN_TXD = LOW; $t < t_{to(dom)TXD}$	1.5	-	3	V
		CAN_TXD = HIGH; recessive; no load	-50	-	+50	mV
$V_{O(rec)}$	recessive output voltage	Normal and Silent modes; CAN_TXD = HIGH; no load	2	$0.5V_{CC}$	3	V
$V_{th(RX)dif}$	differential receiver threshold voltage	Normal and Silent modes $V_{cm(CAN)} [2] = -12\text{ V}$ to $+12\text{ V}$	0.5	0.7	0.9	V
$V_{hys(RX)dif}$	differential receiver hysteresis voltage	Normal and Silent modes $V_{cm(CAN)} = -12\text{ V}$ to $+12\text{ V}$	50	120	400	mV
$I_{O(dom)}$	dominant output current	CAN_TXD = LOW; $t < t_{to(dom)TXD}$ ; $V_{CC} = 5\text{ V}$				
		pin CANH; $V_{CANH} = 0\text{ V}$	-120	-70	-40	mA
		pin CANL; $V_{CANL} = 5\text{ V}/40\text{ V}$	40	70	120	mA

**Table 8.** Static characteristics ...continued

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.5\text{ V}$  to  $5.5\text{ V}$ ;  $R_L = 60\text{ }\Omega$ ; unless otherwise specified; all voltages are defined with respect to ground; positive currents flow into the IC. Also see [Figure 29](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{O(rec)}$	recessive output current	Normal and Silent modes; CAN_TXD = HIGH; $V_{CANH} = V_{CANL} = -27\text{ V}$ to $+32\text{ V}$	-5	-	+5	mA
$I_L$	leakage current	$V_{CC} = 0\text{ V}$ ; $V_{CANH} = V_{CANL} = 5\text{ V}$	-5	0	+5	$\mu\text{A}$
$R_i$	input resistance		9	15	28	$\text{k}\Omega$
$\Delta R_i$	input resistance deviation	between $V_{CANH}$ and $V_{CANL}$	-3	0	+3	%
$R_{i(dif)}$	differential input resistance		19	30	52	$\text{k}\Omega$
$C_{i(cm)}$	common-mode input capacitance		-	-	20	pF
$C_{i(dif)}$	differential input capacitance		-	-	10	pF
<b>Temperature protection</b>						
$T_{j(sd)}$	shutdown junction temperature		-	190	-	$^{\circ}\text{C}$

[1]  $V_{DD\_CAN}$  must be equal to the  $V_{DD}$  of the microcontroller

[2]  $V_{cm(CAN)}$  is the common mode voltage of CANH and CANL.

**Table 9.** Dynamic characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.5\text{ V}$  to  $5.5\text{ V}$ ;  $R_L = 60\text{ }\Omega$  unless specified otherwise. All voltages are defined with respect to ground. Positive currents flow into the IC.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{to(dom)TXD}$	TXD dominant time-out time	CAN_TXD = LOW; Normal mode	0.3	1	12	ms

### 9.3 BOD static characteristics

**Table 10. BOD static characteristics<sup>[1]</sup>**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ .

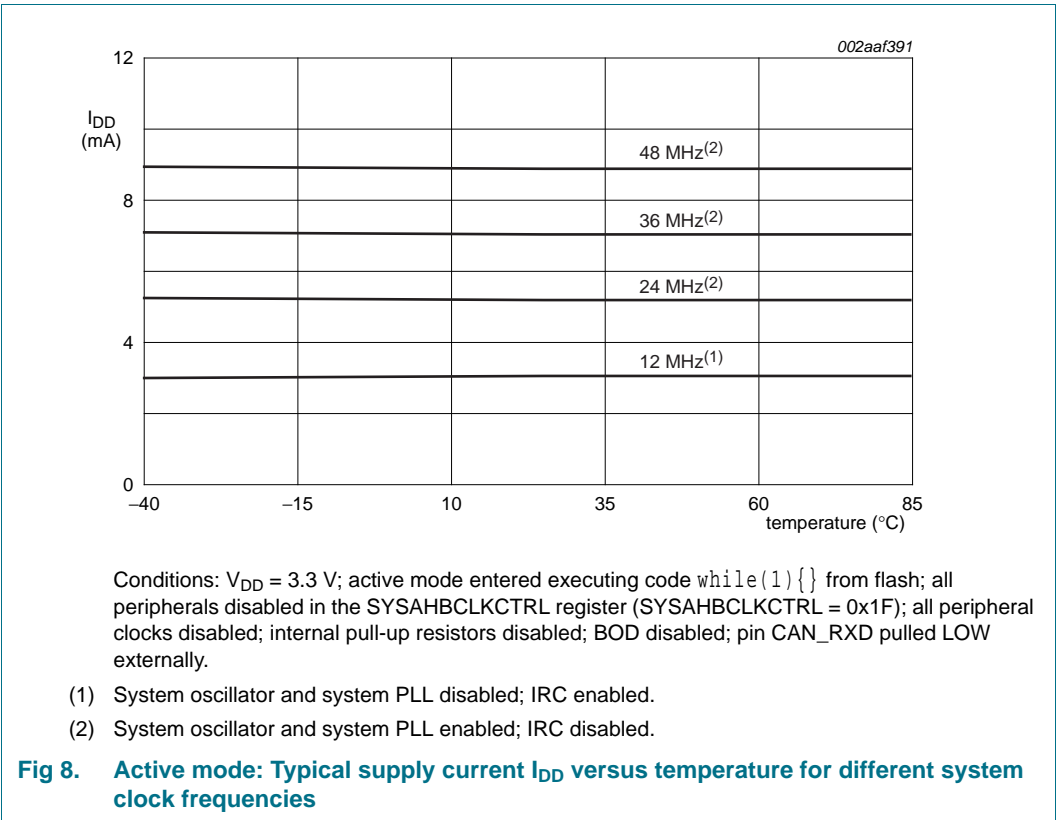
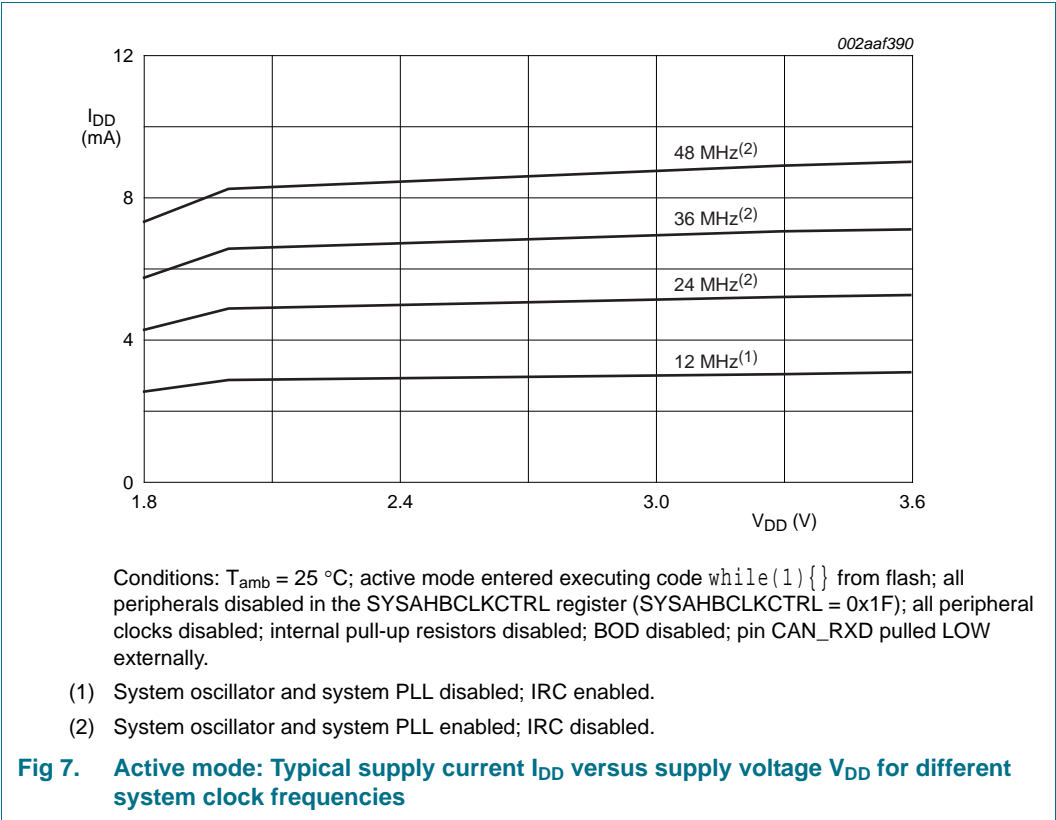
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{th}$	threshold voltage	interrupt level 1				
		assertion	-	2.22	-	V
		de-assertion	-	2.35	-	V
		interrupt level 2				
		assertion	-	2.52	-	V
		de-assertion	-	2.66	-	V
		interrupt level 3				
		assertion	-	2.80	-	V
		de-assertion	-	2.90	-	V
		reset level 0				
		assertion	-	1.46	-	V
		de-assertion	-	1.63	-	V
		reset level 1				
		assertion	-	2.06	-	V
		de-assertion	-	2.15	-	V
		reset level 2				
		assertion	-	2.35	-	V
		de-assertion	-	2.43	-	V
		reset level 3				
		assertion	-	2.63	-	V
		de-assertion	-	2.71	-	V

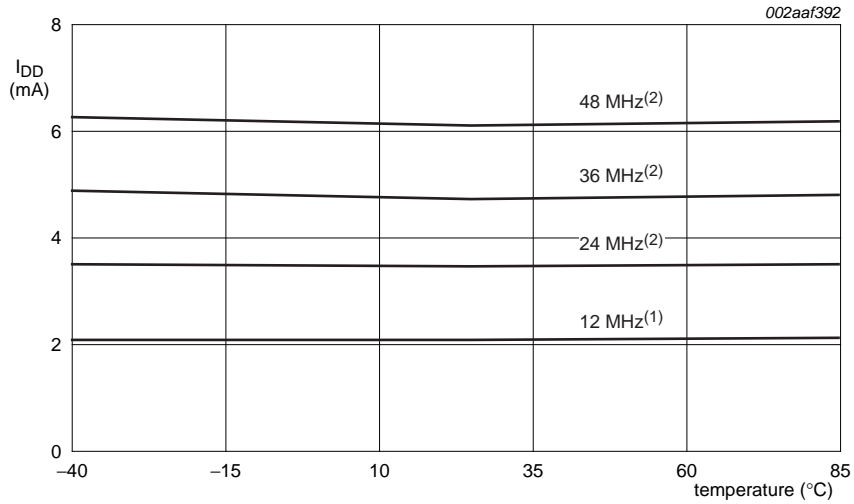
[1] Interrupt levels are selected by writing the level value to the BOD control register BODCTRL, see *LPC11Cx user manual*.

### 9.4 Power consumption

Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC11Cx user manual*):

- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIODIR registers.
- Write 0 to all GPIODATA registers to drive the outputs LOW.

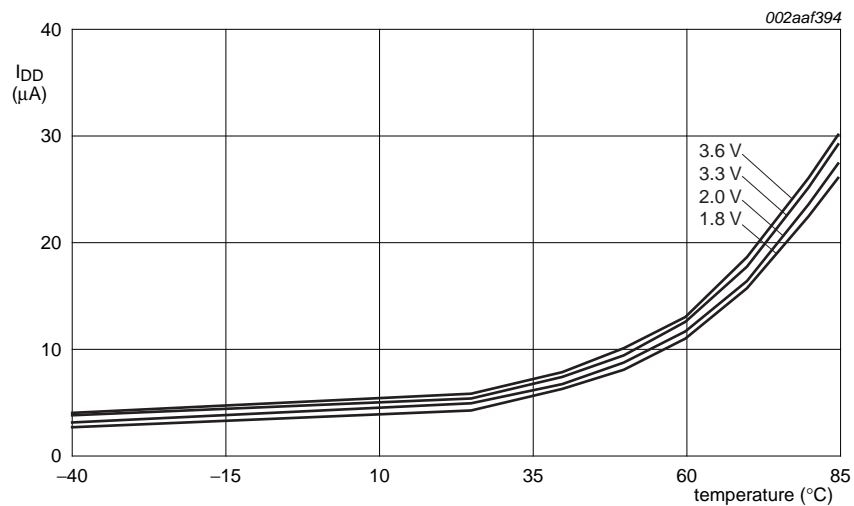




Conditions:  $V_{DD} = 3.3$  V; sleep mode entered from flash; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; internal pull-up resistors disabled; BOD disabled; pin CAN\_RXD pulled LOW externally.

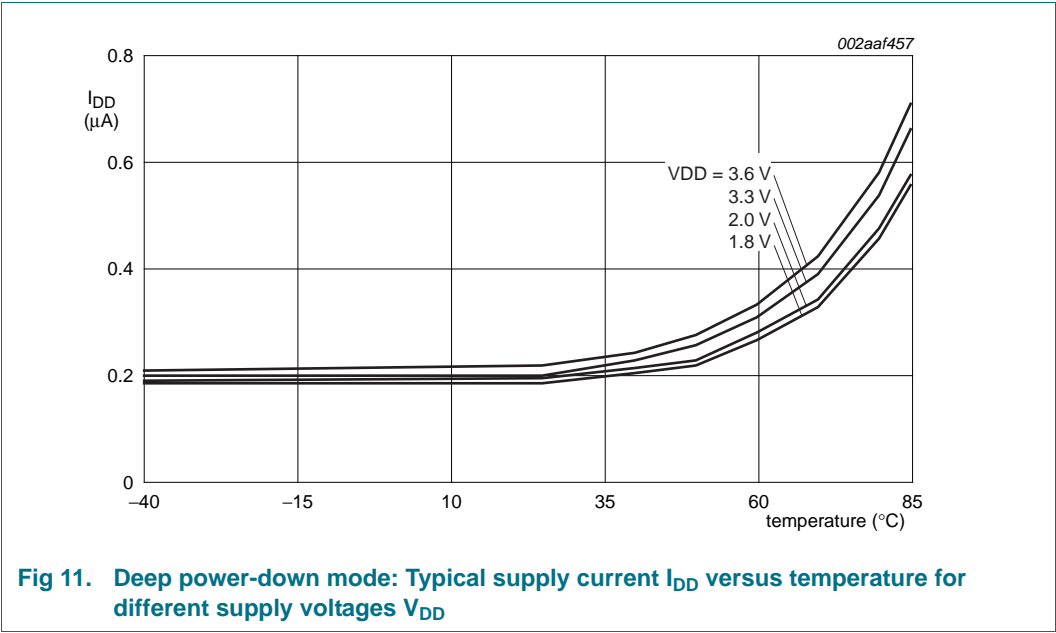
- (1) System oscillator and system PLL disabled; IRC enabled.
- (2) System oscillator and system PLL enabled; IRC disabled.

**Fig 9. Sleep mode: Typical supply current  $I_{DD}$  versus temperature for different system clock frequencies**



Conditions: BOD disabled; all oscillators and analog blocks disabled in the PDSLEEPCFG register (PDSLEEPCFG = 0x0000 18FF); pin CAN\_RXD pulled LOW externally.

**Fig 10. Deep-sleep mode: Typical supply current  $I_{DD}$  versus temperature for different supply voltages  $V_{DD}$**



## 9.5 Peripheral power consumption

The supply current per peripheral is measured as the difference in supply current between the peripheral block enabled and the peripheral block disabled in the SYSAHBCLKCFG and PDRUNCFG (for analog blocks) registers. All other blocks are disabled in both registers and no code is executed. Measured on a typical sample at  $T_{amb} = 25\text{ }^{\circ}\text{C}$ . Unless noted otherwise, the system oscillator and PLL are running in both measurements.

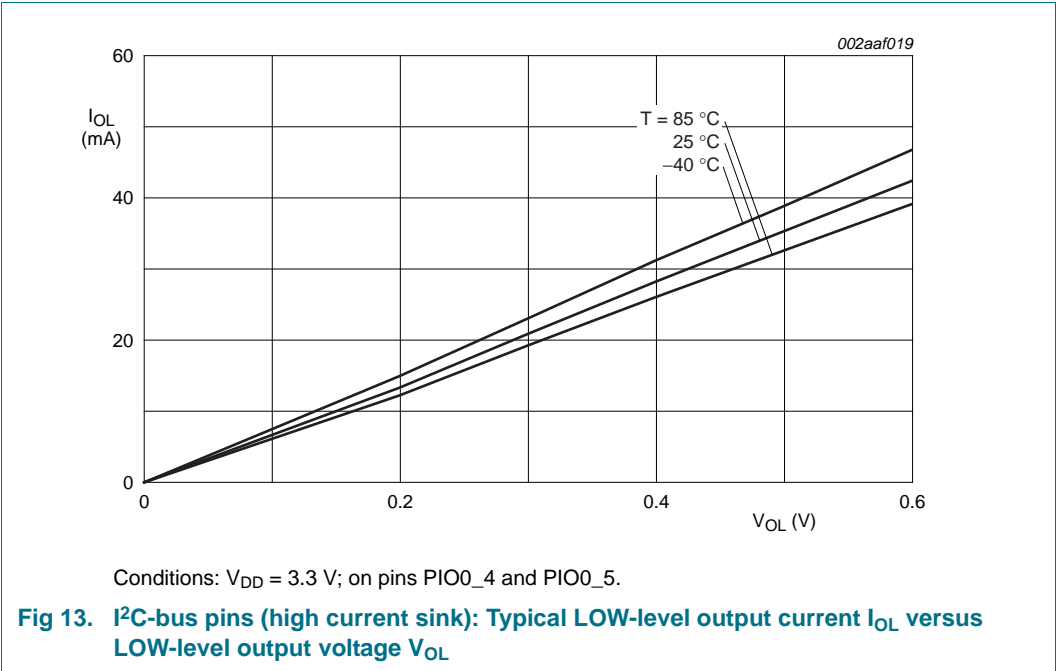
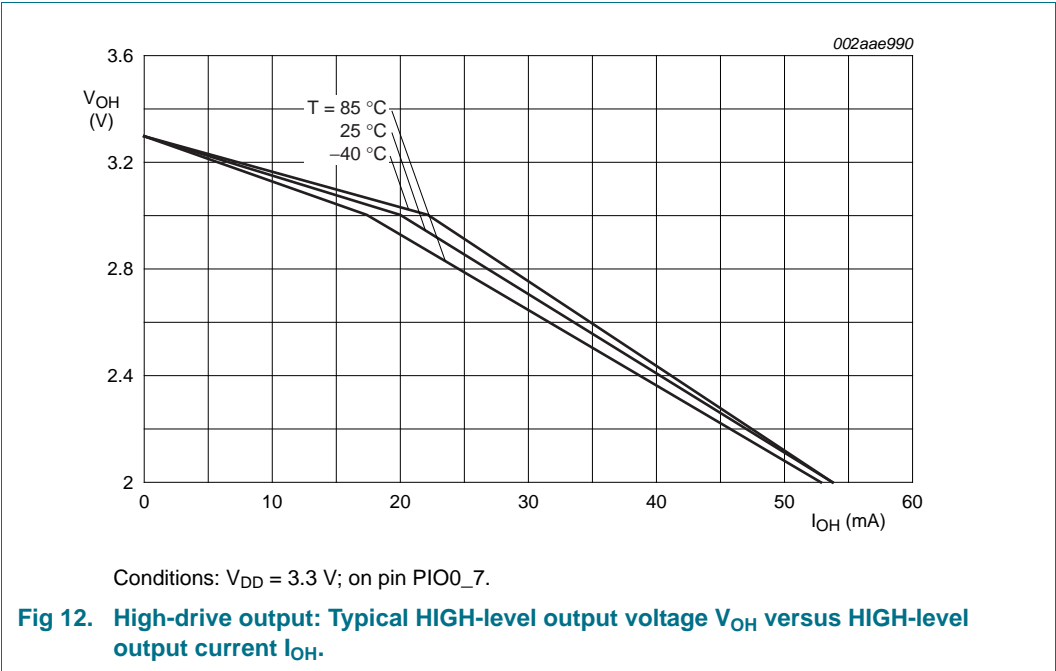
The supply currents are shown for system clock frequencies of 12 MHz and 48 MHz.

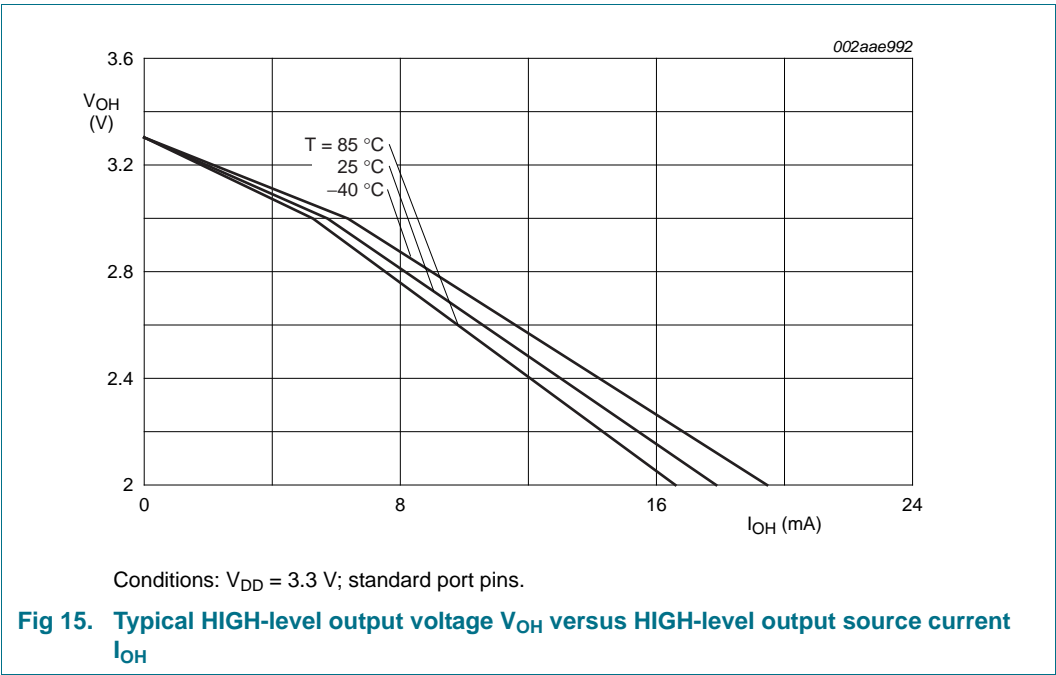
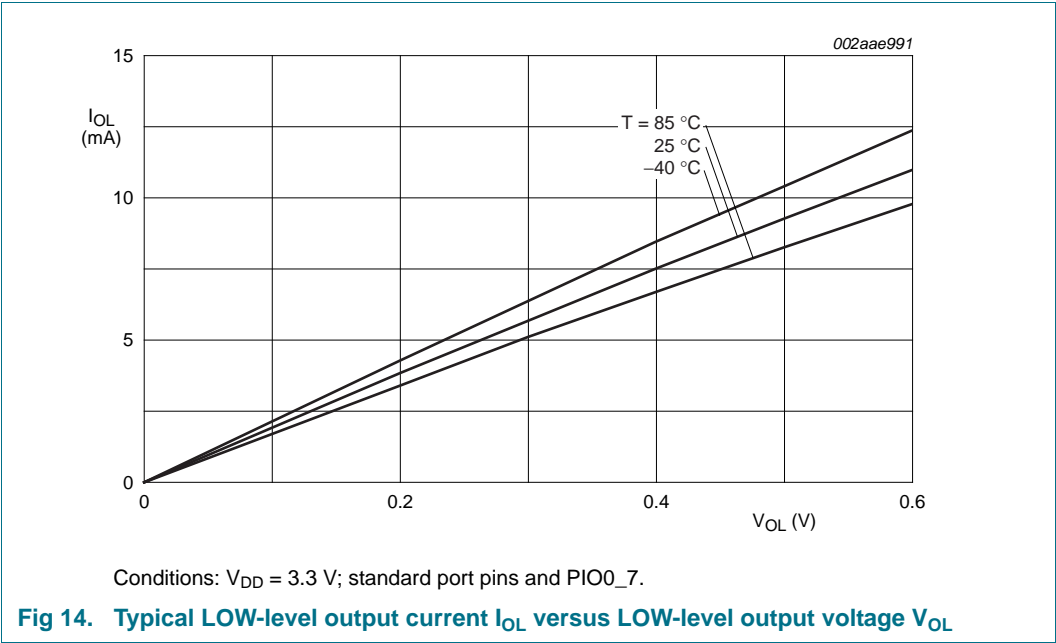
**Table 11. Power consumption for individual analog and digital blocks**

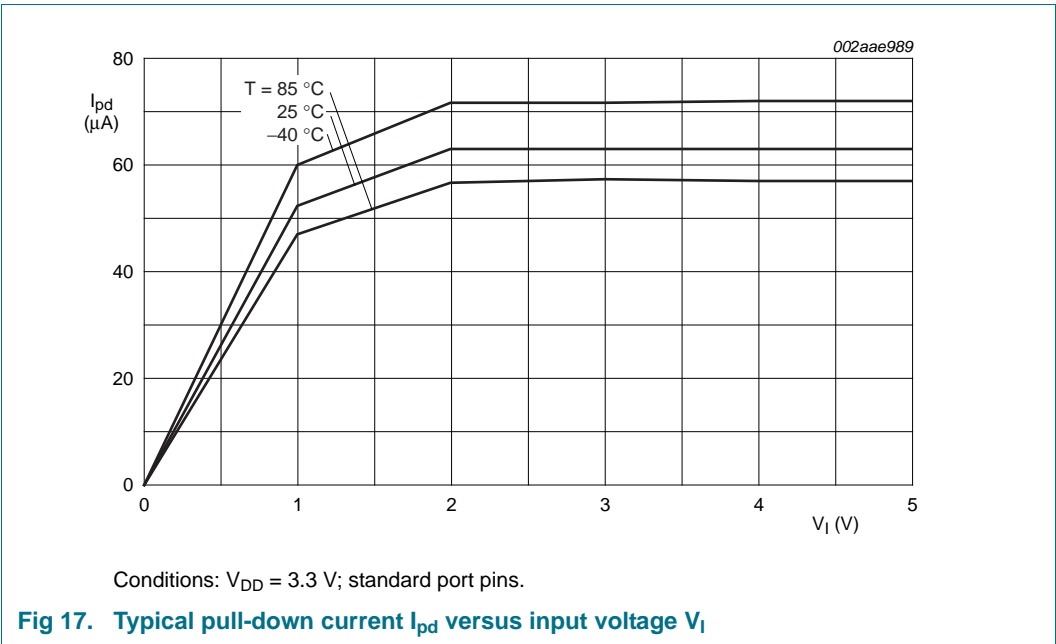
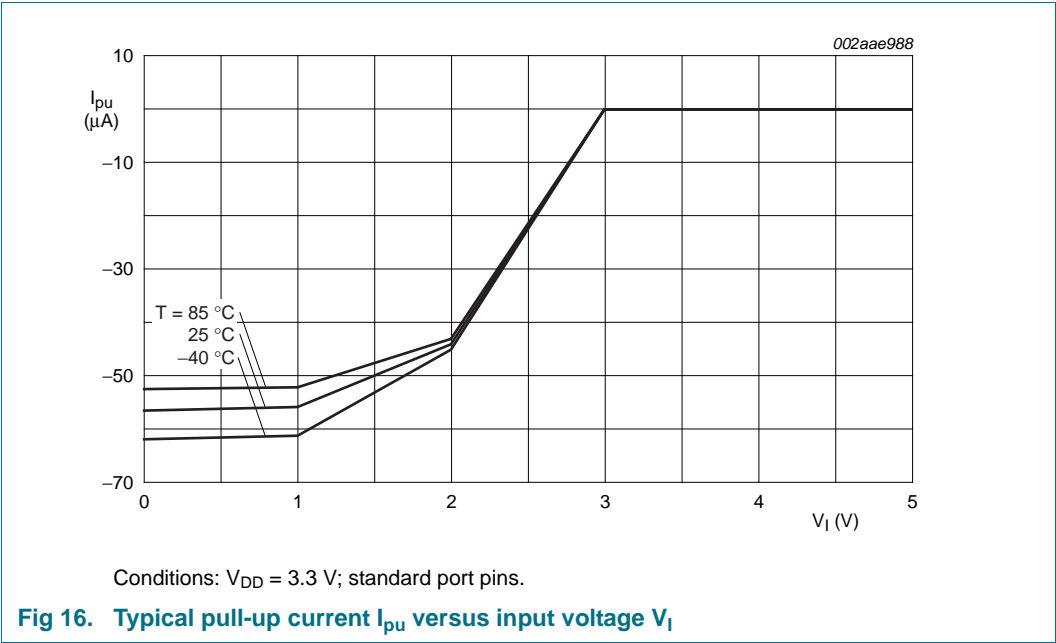
Peripheral	Typical supply current in mA			Notes
	n/a	12 MHz	48 MHz	
IRC	0.27	-	-	System oscillator running; PLL off; independent of main clock frequency.
System oscillator at 12 MHz	0.22	-	-	IRC running; PLL off; independent of main clock frequency.
Watchdog oscillator at 500 kHz/2	0.004	-	-	System oscillator running; PLL off; independent of main clock frequency.
BOD	0.051	-	-	Independent of main clock frequency.
Main PLL	-	0.21	-	
ADC	-	0.08	0.29	
CLKOUT	-	0.12	0.47	Main clock divided by 4 in the CLKOUTDIV register.
CT16B0	-	0.02	0.06	
CT16B1	-	0.02	0.06	
CT32B0	-	0.02	0.07	
CT32B1	-	0.02	0.06	
GPIO	-	0.23	0.88	GPIO pins configured as outputs and set to LOW. Direction and pin state are maintained if the GPIO is disabled in the SYSAHBCLKCFG register.
IOCONFIG	-	0.03	0.10	
I2C	-	0.04	0.13	
ROM	-	0.04	0.15	
SPI0	-	0.12	0.45	
SPI1	-	0.12	0.45	
UART	-	0.22	0.82	
C_CAN	-	0.03	0.1	
WDT	-	0.02	0.06	Main clock selected as clock source for the WDT.



9.6 Electrical pin characteristics







## 10. Dynamic characteristics

### 10.1 Power-up ramp conditions

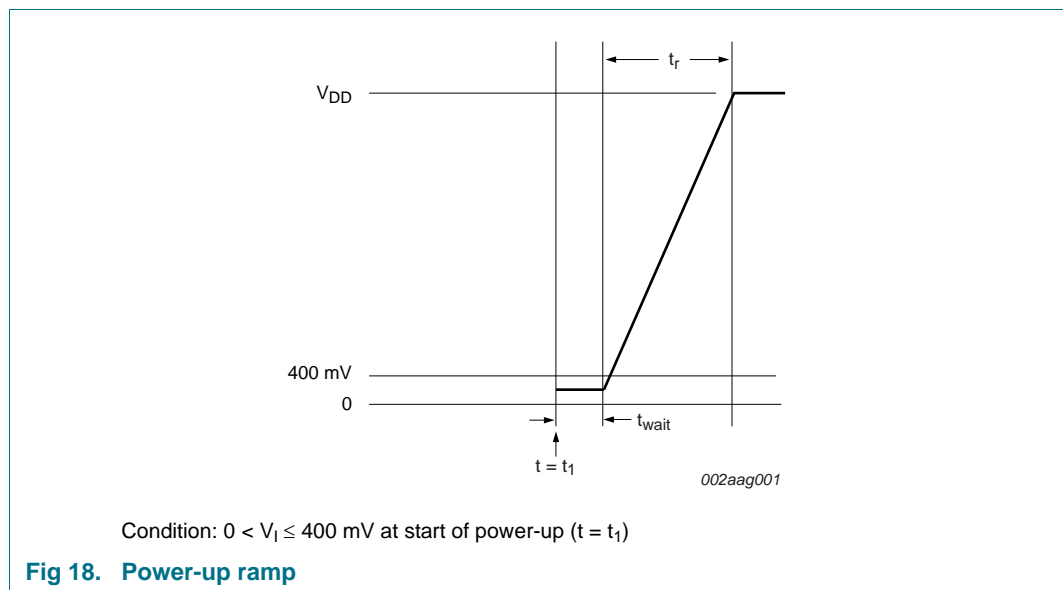
**Table 12. Power-up characteristics**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_r$	rise time	at $t = t_1$ : $0 < V_I \leq 400\text{ mV}$	[1] 0	-	500	ms
$t_{wait}$	wait time		[1][2] 12	-	-	$\mu\text{s}$
$V_I$	input voltage	at $t = t_1$ on pin $V_{DD}$	0	-	400	mV

[1] See [Figure 18](#).

[2] The wait time specifies the time the power supply must be at levels below 400 mV before ramping up.



**Fig 18. Power-up ramp**

### 10.2 Flash memory

**Table 13. Flash characteristics**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$N_{endu}$	endurance		[1] 10000	100000	-	cycles
$t_{ret}$	retention time	powered	10	-	-	years
		unpowered	20	-	-	years
$t_{er}$	erase time	sector or multiple consecutive sectors	95	100	105	ms
$t_{prog}$	programming time		[2] 0.95	1	1.05	ms

[1] Number of program/erase cycles.

[2] Programming times are given for writing 256 bytes from RAM to the flash. Data must be written to the flash in blocks of 256 bytes.

### 10.3 External clock

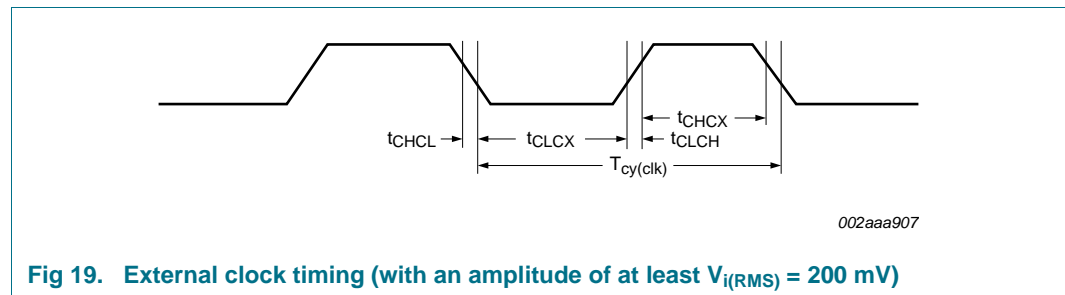
**Table 14. Dynamic characteristic: external clock**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ ;  $V_{DD}$  over specified ranges.<sup>[1]</sup>

Symbol	Parameter	Conditions	Min	Typ <sup>[2]</sup>	Max	Unit
$f_{osc}$	oscillator frequency		1	-	25	MHz
$T_{cy(clk)}$	clock cycle time		40	-	1000	ns
$t_{CHCX}$	clock HIGH time		$T_{cy(clk)} \times 0.4$	-	-	ns
$t_{CLCX}$	clock LOW time		$T_{cy(clk)} \times 0.4$	-	-	ns
$t_{CLCH}$	clock rise time		-	-	5	ns
$t_{CHCL}$	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



**Fig 19. External clock timing (with an amplitude of at least  $V_{i(RMS)} = 200\text{ mV}$ )**

## 10.4 Internal oscillators

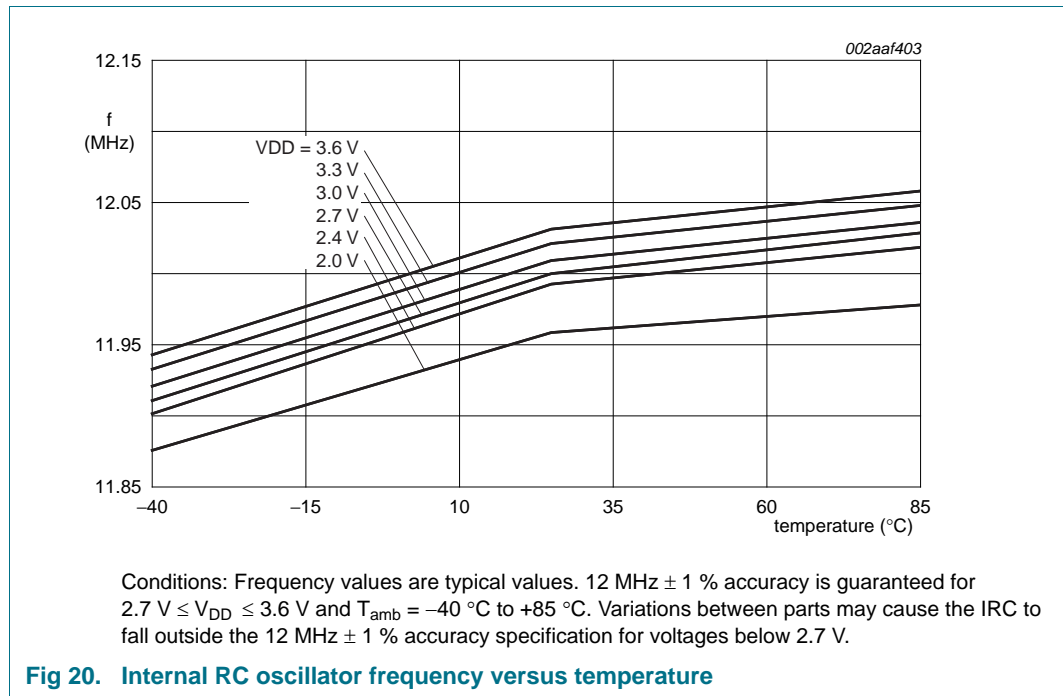
**Table 15. Dynamic characteristic: internal oscillators**

$T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ ;  $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$ .<sup>[1]</sup>

Symbol	Parameter	Conditions	Min	Typ <sup>[2]</sup>	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-	11.88	12	12.12	MHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



**Fig 20. Internal RC oscillator frequency versus temperature**

**Table 16. Dynamic characteristics: Watchdog oscillator**

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$f_{osc(int)}$	internal oscillator frequency	DIVSEL = 0x1F, FREQSEL = 0x1 in the WDTOSCCTRL register;	<sup>[2][3]</sup> -	7.8	-	kHz
		DIVSEL = 0x00, FREQSEL = 0xF in the WDTOSCCTRL register	<sup>[2][3]</sup> -	1700	-	kHz

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The typical frequency spread over processing and temperature ( $T_{amb} = -40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ ) is  $\pm 40\%$ .

[3] See the *LPC11Cx user manual*.

## 10.5 I/O pins

**Table 17. Dynamic characteristic: I/O pins<sup>[1]</sup>**

$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}; 3.0\text{ V} \leq V_{DD} \leq 3.6\text{ V}.$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_r$	rise time	pin configured as output	3.0	-	5.0	ns
$t_f$	fall time	pin configured as output	2.5	-	5.0	ns

[1] Applies to standard port pins and  $\overline{\text{RESET}}$  pin.

## 10.6 I<sup>2</sup>C-bus

**Table 18. Dynamic characteristic: I<sup>2</sup>C-bus pins<sup>[1]</sup>**

$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}.$ <sup>[2]</sup>

Symbol	Parameter	Conditions	Min	Max	Unit
$f_{\text{SCL}}$	SCL clock frequency	Standard-mode	0	100	kHz
		Fast-mode	0	400	kHz
		Fast-mode Plus	0	1	MHz
$t_f$	fall time	<sup>[4][5][6][7]</sup> of both SDA and SCL signals	-	300	ns
		Standard-mode			
		Fast-mode	$20 + 0.1 \times C_b$	300	ns
$t_{\text{LOW}}$	LOW period of the SCL clock	Fast-mode Plus	-	120	ns
		Standard-mode	4.7	-	$\mu\text{s}$
		Fast-mode	1.3	-	$\mu\text{s}$
$t_{\text{HIGH}}$	HIGH period of the SCL clock	Fast-mode Plus	0.5	-	$\mu\text{s}$
		Standard-mode	4.0	-	$\mu\text{s}$
		Fast-mode	0.6	-	$\mu\text{s}$
$t_{\text{HD;DAT}}$	data hold time	Fast-mode Plus	0.26	-	$\mu\text{s}$
		Standard-mode	0	-	$\mu\text{s}$
		Fast-mode	0	-	$\mu\text{s}$
$t_{\text{SU;DAT}}$	data set-up time	Fast-mode Plus	0	-	$\mu\text{s}$
		Standard-mode	250	-	ns
		Fast-mode	100	-	ns
$t_{\text{SU;DAT}}$	data set-up time	Fast-mode Plus	50	-	ns
		Standard-mode	250	-	ns

[1] See the I<sup>2</sup>C-bus specification *UM10204* for details.

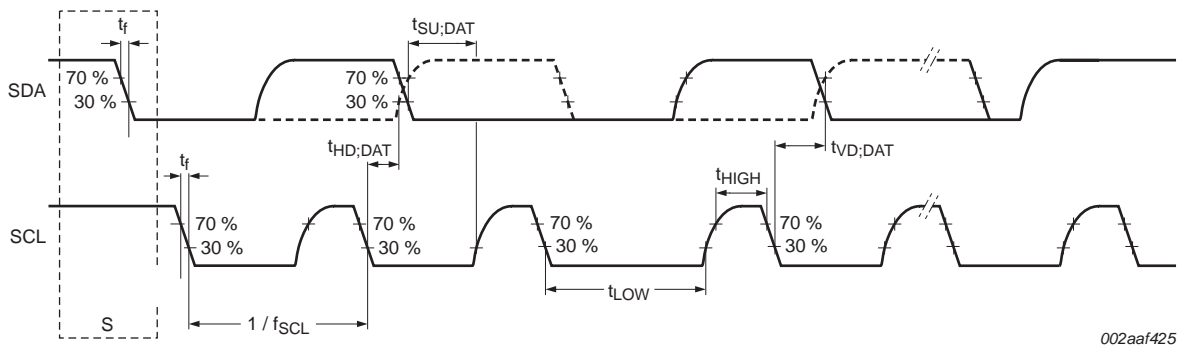
[2] Parameters are valid over operating temperature range unless otherwise specified.

[3]  $t_{\text{HD;DAT}}$  is the data hold time that is measured from the falling edge of SCL; applies to data in transmission and the acknowledge.

[4] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the  $V_{\text{IH(min)}}$  of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[5]  $C_b$  = total capacitance of one bus line in pF.

- [6] The maximum  $t_f$  for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage  $t_f$  is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified  $t_f$ .
- [7] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.
- [8] The maximum  $t_{HD,DAT}$  could be 3.45  $\mu$ s and 0.9  $\mu$ s for Standard-mode and Fast-mode but must be less than the maximum of  $t_{VD,DAT}$  or  $t_{VD,ACK}$  by a transition time (see *UM10204*). This maximum must only be met if the device does not stretch the LOW period ( $t_{LOW}$ ) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.
- [9]  $t_{SU,DAT}$  is the data set-up time that is measured with respect to the rising edge of SCL; applies to data in transmission and the acknowledge.
- [10] A Fast-mode I<sup>2</sup>C-bus device can be used in a Standard-mode I<sup>2</sup>C-bus system but the requirement  $t_{SU,DAT} = 250$  ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line  $t_{r(max)} + t_{SU,DAT} = 1000 + 250 = 1250$  ns (according to the Standard-mode I<sup>2</sup>C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

Fig 21. I<sup>2</sup>C-bus pins clock timing

## 10.7 SPI interfaces

Table 19. Dynamic characteristics of SPI pins in SPI mode

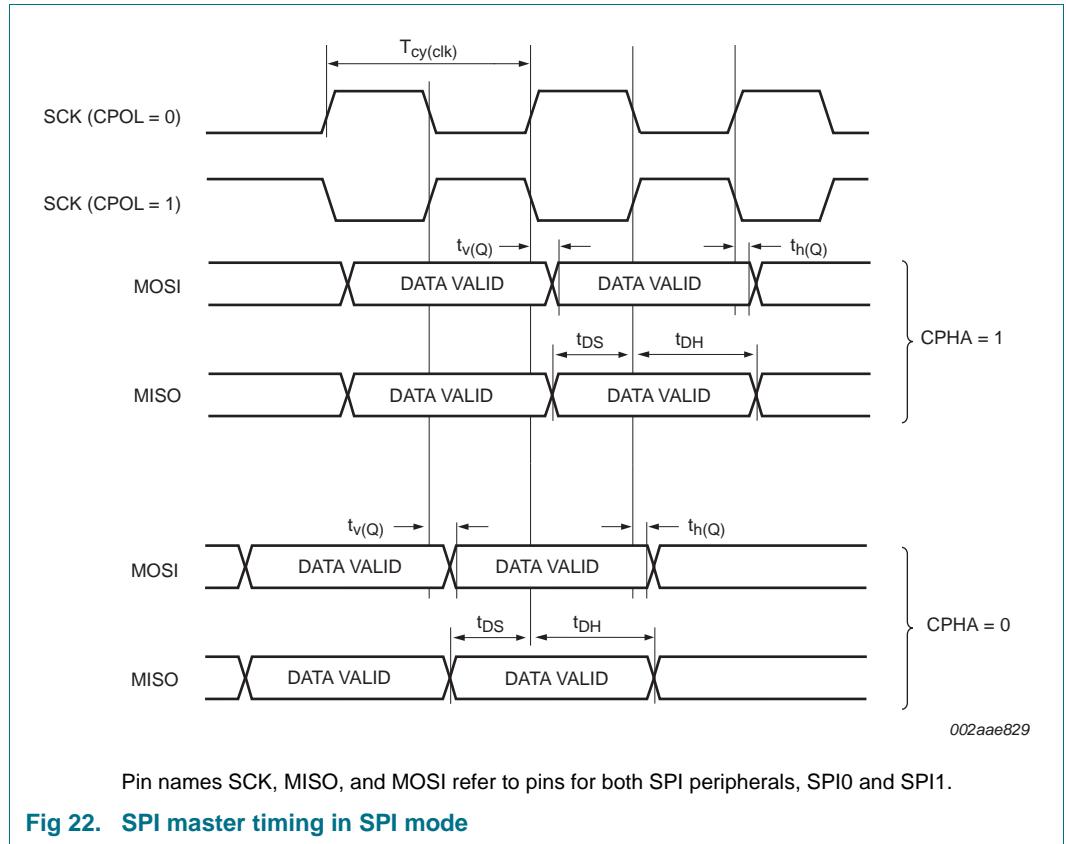
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>SPI master (in SPI mode)</b>						
$T_{cy(clk)}$	clock cycle time	full-duplex mode [1]	50	-	-	ns
		when only transmitting [1]	40	-	-	ns
$t_{DS}$	data set-up time	in SPI mode [2]	15	-	-	ns
		$2.4\text{ V} \leq V_{DD} \leq 3.6\text{ V}$				
		$2.0\text{ V} \leq V_{DD} < 2.4\text{ V}$ [2]	20	-	-	ns
		$1.8\text{ V} \leq V_{DD} < 2.0\text{ V}$ [2]	24	-	-	ns
$t_{DH}$	data hold time	in SPI mode [2]	0	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode [2]	-	-	10	ns
$t_{h(Q)}$	data output hold time	in SPI mode [2]	0	-	-	ns
<b>SPI slave (in SPI mode)</b>						
$T_{cy(PCLK)}$	PCLK cycle time		20	-	-	ns

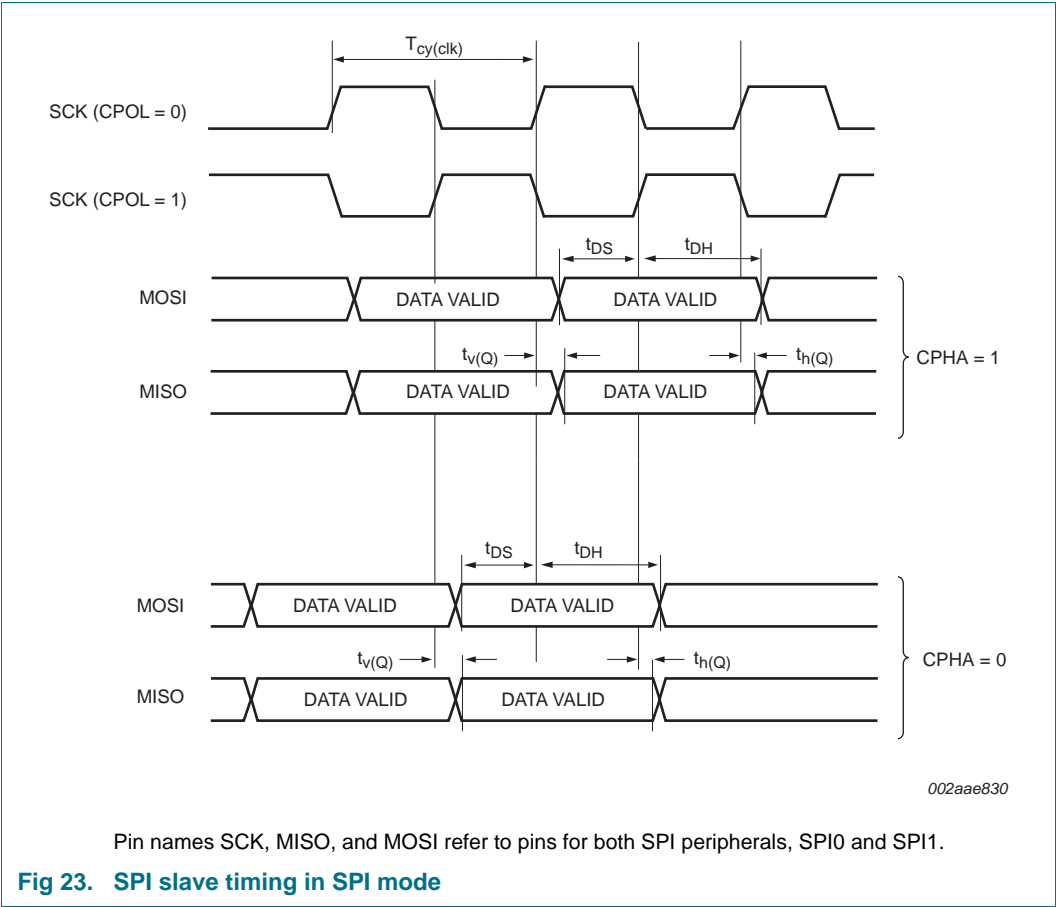


**Table 19. Dynamic characteristics of SPI pins in SPI mode**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{DS}$	data set-up time	in SPI mode	[3][4] 0	-	-	ns
$t_{DH}$	data hold time	in SPI mode	[3][4] $3 \times T_{cy(PCLK)} + 4$	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[3][4] -	-	$3 \times T_{cy(PCLK)} + 11$	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[3][4] -	-	$2 \times T_{cy(PCLK)} + 5$	ns

- [1]  $T_{cy(clk)} = (SSPCLKDIV \times (1 + SCR) \times CPDVSRR) / f_{main}$ . The clock cycle time derived from the SPI bit rate  $T_{cy(clk)}$  is a function of the main clock frequency  $f_{main}$ , the SPI peripheral clock divider (SSPCLKDIV), the SPI SCR parameter (specified in the SSP0CR0 register), and the SPI CPDVSRR parameter (specified in the SPI clock prescale register).
- [2]  $T_{amb} = -40\text{ °C to }85\text{ °C}$ .
- [3]  $T_{cy(clk)} = 12 \times T_{cy(PCLK)}$ .
- [4]  $T_{amb} = 25\text{ °C}$ ; for normal voltage supply range:  $V_{DD} = 3.3\text{ V}$ .





## 11. Application information

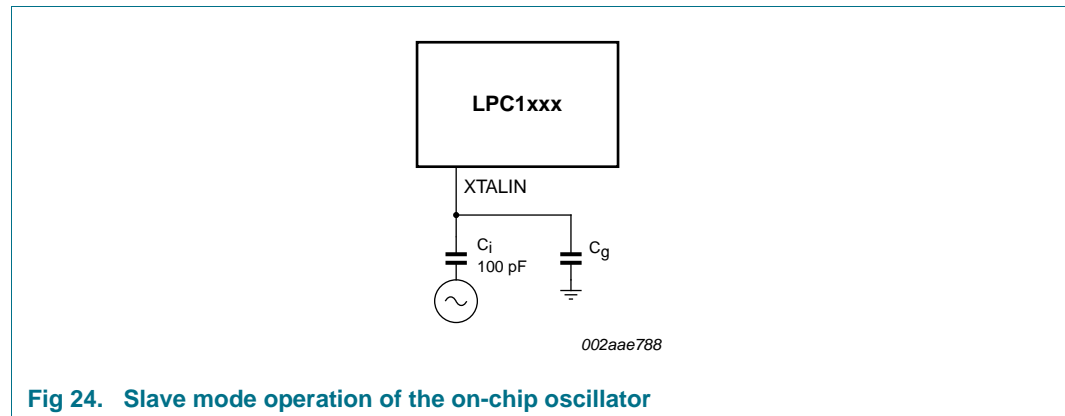
### 11.1 ADC usage notes

The following guidelines show how to increase the performance of the ADC in a noisy environment beyond the ADC specifications listed in [Table 7](#):

- The ADC input trace must be short and as close as possible to the LPC11Cx2/Cx4 chip.
- The ADC input traces must be shielded from fast switching digital signals and noisy power supply lines.
- Because the ADC and the digital core share the same power supply, the power supply line must be adequately filtered.
- To improve the ADC performance in a very noisy environment, put the device in Sleep mode during the ADC conversion.

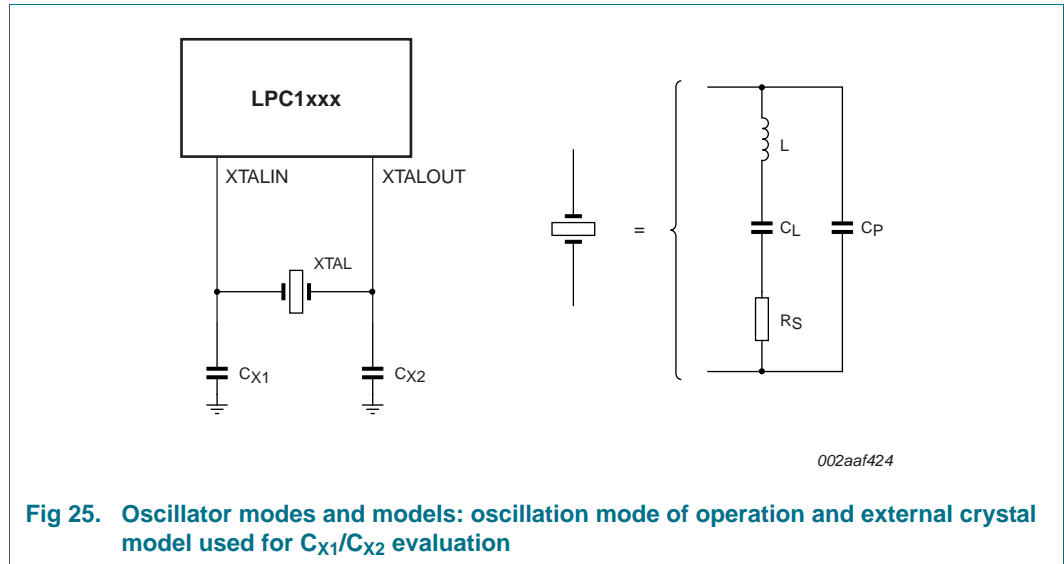
### 11.2 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with  $C_i = 100$  pF. To limit the input voltage to the specified range, choose an additional capacitor to ground  $C_g$  which attenuates the input voltage by a factor  $C_i/(C_i + C_g)$ . In slave mode, a minimum of 200 mv (RMS) is needed.



In slave mode the input clock signal should be coupled by means of a capacitor of 100 pF ([Figure 24](#)), with an amplitude between 200 mv (RMS) and 1000 mv (RMS). This corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTALOUT pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in [Figure 25](#) and in [Table 20](#) and [Table 21](#). Since the feedback resistance is integrated on chip, only a crystal and the capacitances  $C_{X1}$  and  $C_{X2}$  need to be connected externally in case of fundamental mode oscillation (the fundamental frequency is represented by  $L$ ,  $C_L$  and  $R_S$ ). Capacitance  $C_P$  in [Figure 25](#) represents the parallel package capacitance and should not be larger than 7 pF. Parameters  $F_{OSC}$ ,  $C_L$ ,  $R_S$  and  $C_P$  are supplied by the crystal manufacturer (see [Table 20](#)).



**Table 20. Recommended values for  $C_{X1}/C_{X2}$  in oscillation mode (crystal and external components parameters) low frequency mode**

Fundamental oscillation frequency $F_{osc}$	Crystal load capacitance $C_L$	Maximum crystal series resistance $R_S$	External load capacitors $C_{X1}, C_{X2}$
1 MHz - 5 MHz	10 pF	< 300 $\Omega$	18 pF, 18 pF
	20 pF	< 300 $\Omega$	39 pF, 39 pF
	30 pF	< 300 $\Omega$	57 pF, 57 pF
5 MHz - 10 MHz	10 pF	< 300 $\Omega$	18 pF, 18 pF
	20 pF	< 200 $\Omega$	39 pF, 39 pF
	30 pF	< 100 $\Omega$	57 pF, 57 pF
10 MHz - 15 MHz	10 pF	< 160 $\Omega$	18 pF, 18 pF
	20 pF	< 60 $\Omega$	39 pF, 39 pF
15 MHz - 20 MHz	10 pF	< 80 $\Omega$	18 pF, 18 pF

**Table 21. Recommended values for  $C_{X1}/C_{X2}$  in oscillation mode (crystal and external components parameters) high frequency mode**

Fundamental oscillation frequency $F_{osc}$	Crystal load capacitance $C_L$	Maximum crystal series resistance $R_S$	External load capacitors $C_{X1}, C_{X2}$
15 MHz - 20 MHz	10 pF	< 180 $\Omega$	18 pF, 18 pF
	20 pF	< 100 $\Omega$	39 pF, 39 pF
20 MHz - 25 MHz	10 pF	< 160 $\Omega$	18 pF, 18 pF
	20 pF	< 80 $\Omega$	39 pF, 39 pF

### 11.3 XTAL Printed Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors  $C_{X1}$ ,  $C_{X2}$ , and  $C_{X3}$  in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in

order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of  $C_{x1}$  and  $C_{x2}$  should be chosen smaller accordingly to the increase in parasitics of the PCB layout.

## 11.4 Standard I/O pad configuration

Figure 26 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Analog input

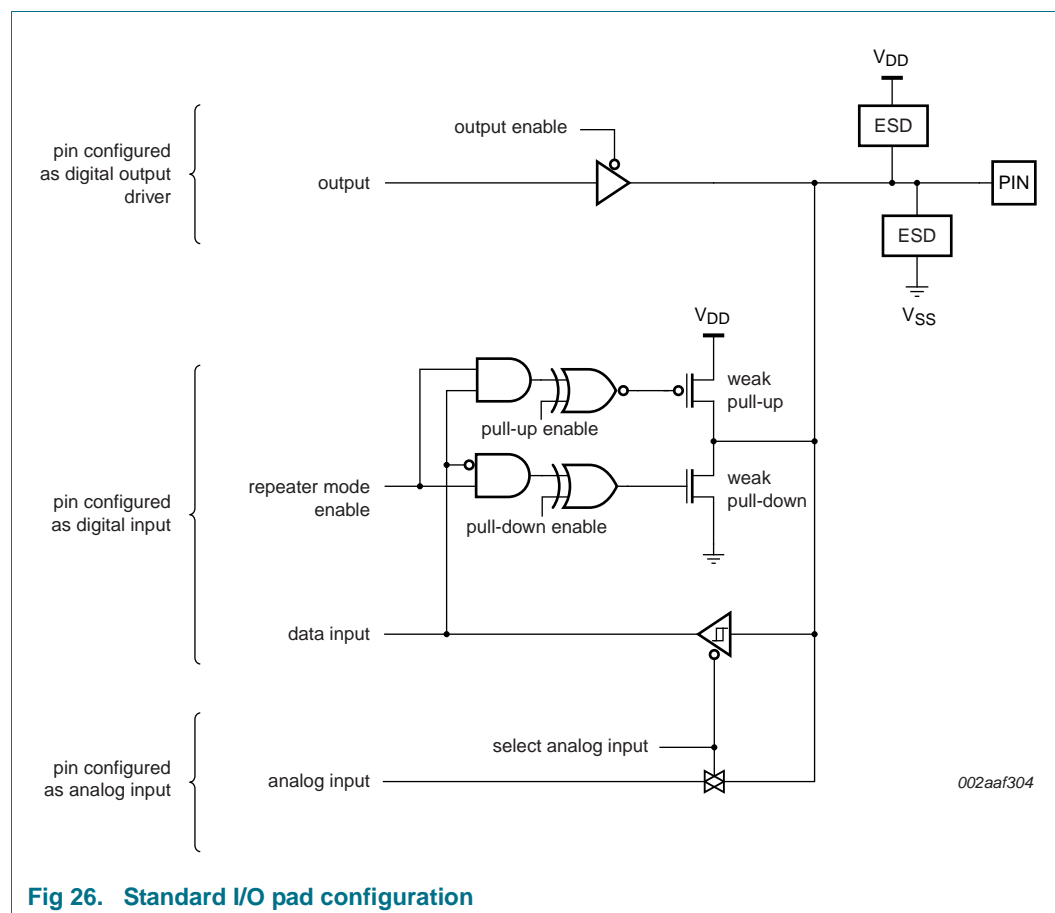


Fig 26. Standard I/O pad configuration

## 11.5 Reset pad configuration

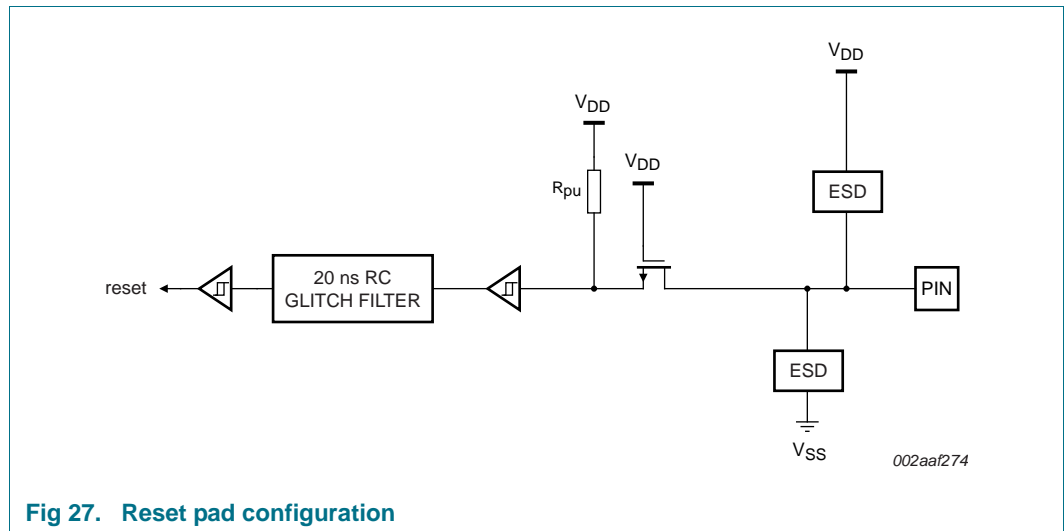


Fig 27. Reset pad configuration

## 11.6 C\_CAN with external transceiver (LPC11C12/C14 only)

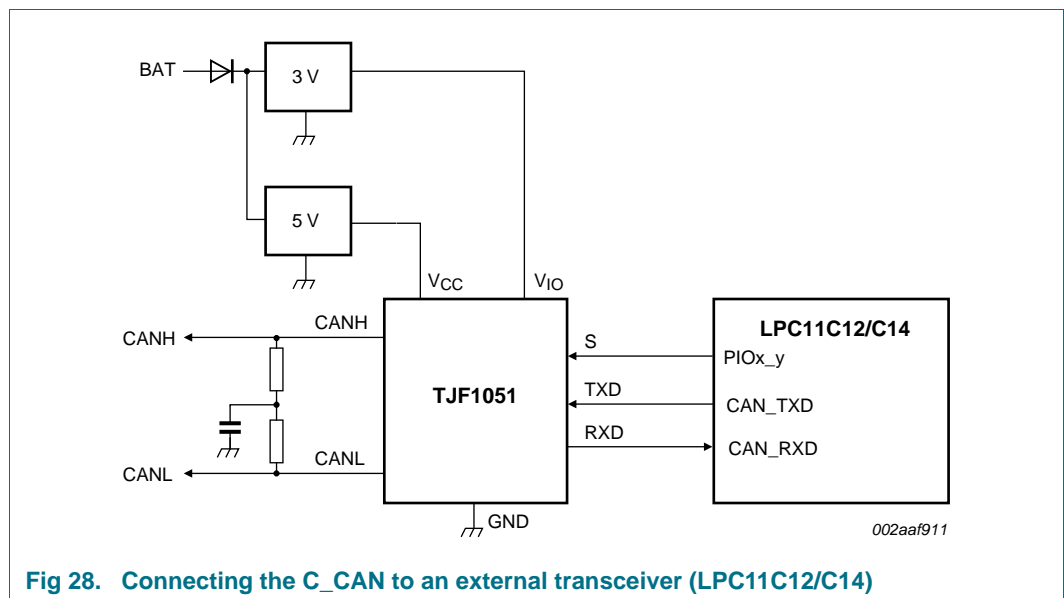


Fig 28. Connecting the C\_CAN to an external transceiver (LPC11C12/C14)

11.7 C\_CAN with on-chip, high-speed transceiver (LPC11C22/C24 only)

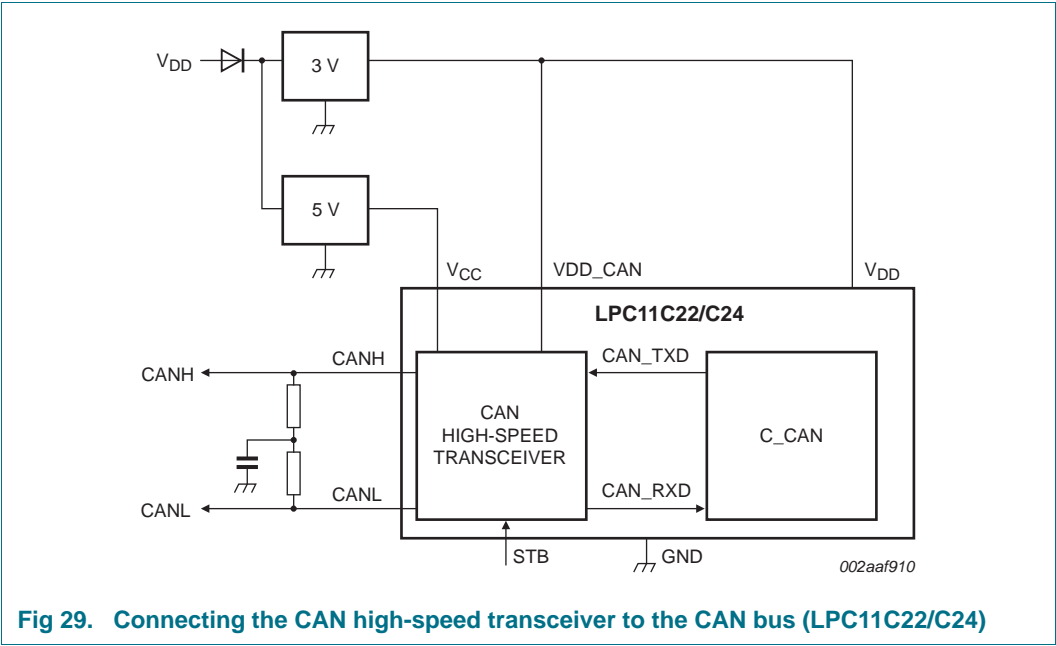


Fig 29. Connecting the CAN high-speed transceiver to the CAN bus (LPC11C22/C24)

12. Package outline

LQFP48: plastic low profile quad flat package; 48 leads; body 7 x 7 x 1.4 mm SOT313-2

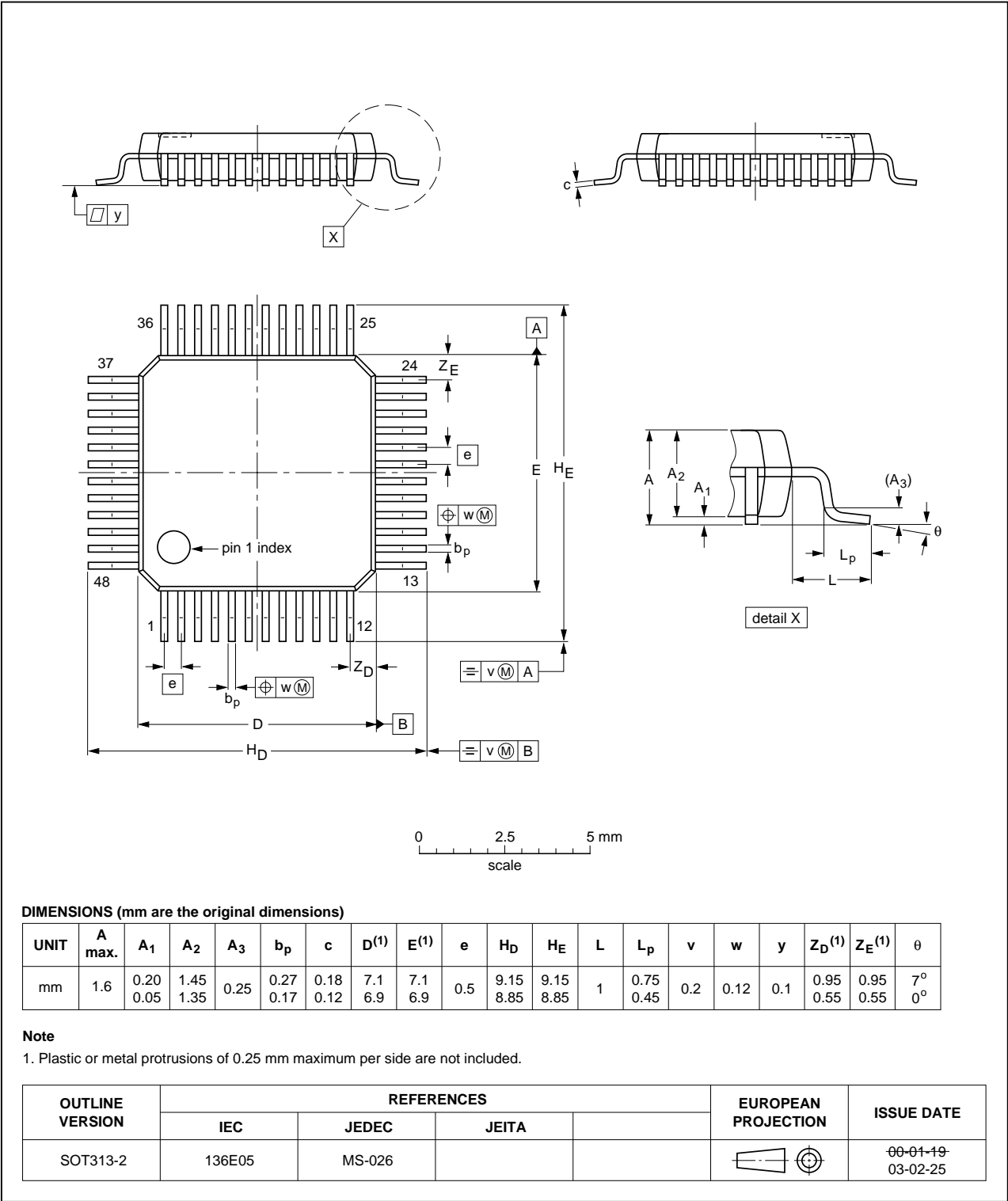


Fig 30. Package outline SOT313-2 (LQFP48)



13. Soldering

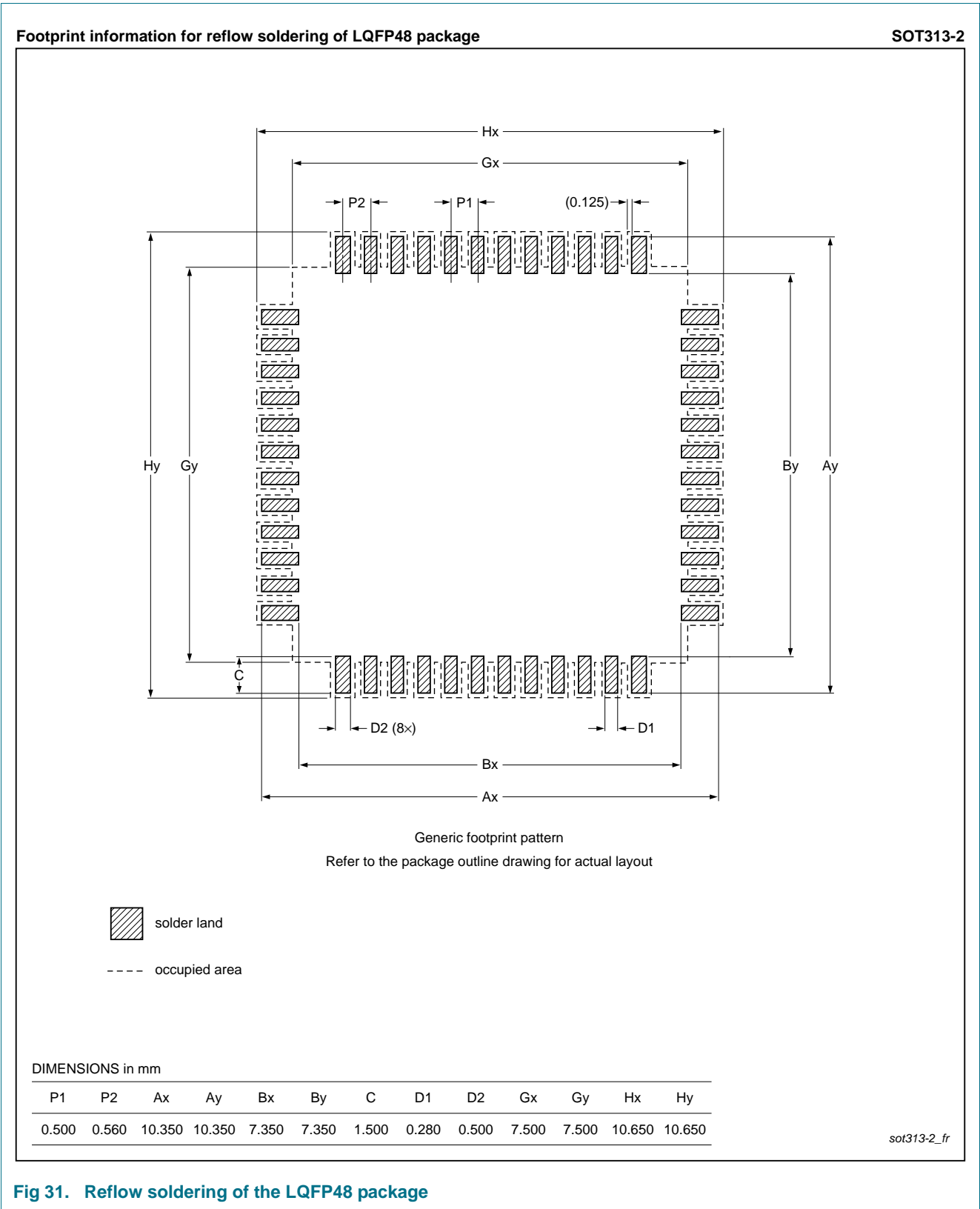


Fig 31. Reflow soldering of the LQFP48 package

## 14. Abbreviations

Table 22. Abbreviations

Acronym	Description
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
API	Application Programming Interface
BOD	BrownOut Detection
CAN	Controller Area Network
GPIO	General Purpose Input/Output
PLL	Phase-Locked Loop
RC	Resistor-Capacitor
SDO	Service Data Object
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter

## 15. Revision history

**Table 23. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC11CX2_CX4 v.3.2	20160104	Product data sheet	-	LPC11CX2_CX4 v.3.1
Modifications:	<ul style="list-style-type: none"> <li>Added <a href="#">Section 10.1 "Power-up ramp conditions"</a>.</li> <li>Added text to <math>V_I</math>, input voltage in <a href="#">Table 5 "Limiting values"</a>: 5 V tolerant I/O pins; <math>V_{DD} \geq 1.8</math> V.</li> <li>Updated <a href="#">Table 6 "Static characteristics"</a>: <ul style="list-style-type: none"> <li>Replaced text, pin configured to provide a digital function to <math>V_{DD} = 0</math> V for <math>V_I</math>, input voltage in Standard port pins, RESET.</li> <li>Replaced text, pin configured to provide a digital function to <math>V_{DD} \geq 1.8</math> V and <math>V_{DD} = 0</math> V for <math>V_I</math>, input voltage in High-drive output pin (PIO0_7).</li> </ul> </li> <li>Removed footnote 12: <math>V_{DD}</math> supply voltage must be present.</li> <li>Updated <a href="#">Figure 29 "Connecting the CAN high-speed transceiver to the CAN bus (LPC11C22/C24)"</a>: Fixed Typo: "STD" changed to "STB".</li> </ul>			
LPC11CX2_CX4 v.3.1	20130515	Product data sheet	-	LPC11CX2_CX4 v.3
Modifications:	<ul style="list-style-type: none"> <li>Table 3 and Table 4: Added "5 V tolerant pad" to RESET/PIO0_0 table note.</li> <li>Table 5: <ul style="list-style-type: none"> <li>Added Table note 2.</li> <li>Corrected <math>V_{DD}</math> min and max.</li> </ul> </li> <li>Table 8: Added Table note 1.</li> <li>Table 10: Removed BOD interrupt level 0.</li> </ul>			
LPC11CX2_CX4 v.3	20110627	Product data sheet	-	LPC11C12_C14 v.2
Modifications:	<ul style="list-style-type: none"> <li>I<sup>2</sup>C-bus pins configured as standard mode pins, parameter <math>I_{OL}</math> changed to 3.5 mA (minimum) for <math>2.0</math> V <math>\leq V_{DD} \leq 3.6</math> V.</li> <li>Parameter <math>V_x</math> added to Table 5 "Limiting values".</li> <li>C_CAN power consumption data added to Table 11.</li> <li>ADC sampling frequency corrected in Table 7 (Table note 7).</li> <li>Reflow soldering footprint drawing added (Section 13).</li> <li>Pull-up level specified in Table 3 and Table 4.</li> <li>Parameter <math>T_{cy(clk)}</math> corrected on Table 18.</li> <li>Condition for parameter <math>T_{stg}</math> in Table 5 updated.</li> <li>Table note 5 of Table 5 updated.</li> <li>Table 18 T~cy(clk) condition changed from "when only receiving" to "full-duplex mode"</li> </ul>			
LPC11CX2_CX4 v.2	20101203	Product data sheet	-	LPC11C12_C14 v.1

Table 23. Revision history ...continued

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	<ul style="list-style-type: none"> <li>• Parts LPC11C22 and LPC11C24 added.</li> <li>• Pin description for parts LPC11C22 and LPC11C24 added (Table 4).</li> <li>• Static characteristics for CAN transceiver added (Table 8).</li> <li>• Description of high-speed, on-chip CAN transceiver added (LPC11C22/C24). See Section 7.11.2.</li> <li>• Application diagram for connecting the C_CAN to an external transceiver added (Section 11.6).</li> <li>• Application diagram for high-speed, on-chip CAN transceiver added (Section 11.7).</li> <li>• Typical value for parameter <math>N_{\text{endu}}</math> added in Table 12 “Flash characteristics”.</li> <li>• Description of <math>\overline{\text{RESET}}</math> and WAKEUP pins updated in Table 3.</li> <li>• PLL output frequency limited to &lt; 100 MHz in Section 7.16.2 “System PLL”.</li> <li>• Parameter <math>V_{\text{hys}}</math> for I<sup>2</sup>C bus pins: typical value corrected <math>V_{\text{hys}} = 0.05V_{\text{DD}}</math> in Table 6.</li> </ul>			
LPC11C12_C14 v.1	20100921	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 16.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

**Short data sheet** — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

**Product specification** — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

### 16.3 Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

**Terms and conditions of commercial sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

**Non-automotive qualified products** — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b)

whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

## 16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

**I<sup>2</sup>C-bus** — logo is a trademark of NXP Semiconductors N.V.

## 17. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

## 18. Contents

<b>1</b>	<b>General description</b>	<b>1</b>	7.16.1.3	Watchdog oscillator	24
<b>2</b>	<b>Features and benefits</b>	<b>1</b>	7.16.2	System PLL	24
<b>3</b>	<b>Applications</b>	<b>2</b>	7.16.3	Clock output	24
<b>4</b>	<b>Ordering information</b>	<b>3</b>	7.16.4	Wake-up process	24
4.1	Ordering options	3	7.16.5	Power control	24
<b>5</b>	<b>Block diagram</b>	<b>4</b>	7.16.5.1	Sleep mode	24
<b>6</b>	<b>Pinning information</b>	<b>5</b>	7.16.5.2	Deep-sleep mode	25
6.1	Pinning	5	7.16.5.3	Deep power-down mode	25
6.2	Pin description	7	7.17	System control	25
<b>7</b>	<b>Functional description</b>	<b>15</b>	7.17.1	Start logic	25
7.1	ARM Cortex-M0 processor	15	7.17.2	Reset	25
7.2	On-chip flash program memory	15	7.17.3	Brownout detection	26
7.3	On-chip SRAM	15	7.17.4	Code security (Code Read Protection - CRP)	26
7.4	Memory map	15	7.17.5	Bootloader	27
7.5	Nested Vectored Interrupt Controller (NVIC)	16	7.17.6	APB interface	27
7.5.1	Features	16	7.17.7	AHB Lite	27
7.5.2	Interrupt sources	17	7.17.8	External interrupt inputs	27
7.6	IOCONFIG block	17	7.18	Emulation and debugging	27
7.7	Fast general purpose parallel I/O	17	<b>8</b>	<b>Limiting values</b>	<b>28</b>
7.7.1	Features	17	<b>9</b>	<b>Static characteristics</b>	<b>29</b>
7.8	UART	18	9.1	ADC characteristics	32
7.8.1	Features	18	9.2	C_CAN on-chip, high-speed transceiver characteristics	34
7.9	SPI serial I/O controller	18	9.3	BOD static characteristics	36
7.9.1	Features	18	9.4	Power consumption	36
7.10	I <sup>2</sup> C-bus serial I/O controller	18	9.5	Peripheral power consumption	40
7.10.1	Features	19	9.6	Electrical pin characteristics	41
7.11	C_CAN controller	19	<b>10</b>	<b>Dynamic characteristics</b>	<b>44</b>
7.11.1	Features	19	10.1	Power-up ramp conditions	44
7.11.2	On-chip, high-speed CAN transceiver	20	10.2	Flash memory	44
7.11.2.1	Features	20	10.3	External clock	45
7.11.2.2	Normal mode	20	10.4	Internal oscillators	46
7.11.2.3	Silent mode	20	10.5	I/O pins	47
7.11.2.4	Undervoltage protection	20	10.6	I <sup>2</sup> C-bus	47
7.11.2.5	Thermal protection	20	10.7	SPI interfaces	48
7.11.2.6	Time-out function	21	<b>11</b>	<b>Application information</b>	<b>51</b>
7.12	10-bit ADC	21	11.1	ADC usage notes	51
7.12.1	Features	21	11.2	XTAL input	51
7.13	General purpose external event counter/timers	21	11.3	XTAL Printed Circuit Board (PCB) layout guidelines	52
7.13.1	Features	21	11.4	Standard I/O pad configuration	53
7.14	System tick timer	22	11.5	Reset pad configuration	54
7.15	Watchdog timer	22	11.6	C_CAN with external transceiver (LPC11C12/C14 only)	54
7.15.1	Features	22	11.7	C_CAN with on-chip, high-speed transceiver (LPC11C22/C24 only)	55
7.16	Clocking and power control	22	<b>12</b>	<b>Package outline</b>	<b>56</b>
7.16.1	Crystal oscillators	22			
7.16.1.1	Internal RC oscillator	23			
7.16.1.2	System oscillator	23			

continued >>

<b>13</b>	<b>Soldering .....</b>	<b>57</b>
<b>14</b>	<b>Abbreviations.....</b>	<b>58</b>
<b>15</b>	<b>Revision history.....</b>	<b>59</b>
<b>16</b>	<b>Legal information.....</b>	<b>61</b>
16.1	Data sheet status .....	61
16.2	Definitions.....	61
16.3	Disclaimers .....	61
16.4	Trademarks.....	62
<b>17</b>	<b>Contact information.....</b>	<b>62</b>
<b>18</b>	<b>Contents .....</b>	<b>63</b>

---

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

---

© NXP B.V. 2016.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

Date of release: 4 January 2016

Document identifier: LPC11CX2\_CX4



# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

NXP:

[LPC11C22FBD48/301,151](#)